

ADS794x Ultra-Low Power, 12-, 10-, and 8-Bit, Dual-Channel, SAR ADCs

1 Features

- Sample rate: 2 MSPS
- Pin-compatible family: 12-, 10-, 8-bit
- High resolution, high throughput:
 - ADS7947: 12 bit, 2.1 MSPS
 - ADS7948: 10 bit, 2.57 MSPS
 - ADS7949: 8 bit, 3 MSPS
- Excellent performance:
 - No missing codes
 - INL: 1 LSB (max)
 - SNR: 72 dB (min)
- Low power:
 - 7.5 mW at 2-MSPS operation
 - Auto power-down at lower speeds:
 - 3.8 mW at 500 kSPS
 - 0.8 mW at 100 kSPS
 - 0.16 mW at 20 kSPS
- Wide supply range:
 - Analog: 2.7 V to 5.5 V
 - Digital: 1.65 V to AVDD
- SPI-compatible serial interface
- Extended temperature range: –40°C to +125°C
- Tiny footprint: 3-mm × 3-mm WQFN

2 Applications

- Communication systems
- Optical networking
- Medical instrumentation
- Battery-powered equipment
- Data acquisition systems

3 Description

The ADS7947, ADS7948, and ADS7949 are pin-compatible 12-bit, 10-bit, and 8-bit, 2-MSPS, analog-to-digital converters (ADCs), respectively. The devices operate at a 2-MSPS sample rate with a standard 16 clock data frame. In addition, the ADS7947 (12-bit) can be operated at 2.1 MSPS, the ADS7948 (10-bit) at 2.57 MSPS, and the ADS7949 (8-bit) at 3 MSPS with a short data frame optimized for the number of clocks sufficient for conversion with no drop in performance. The devices feature both outstanding dc precision and excellent dynamic performance. This family of pin-compatible devices includes a two-channel input multiplexer and a low-power successive approximation register (SAR) ADC.

The ADS7947, ADS7948, and ADS7949 support a wide analog supply range that supports the full-scale input range up to 5 V. A simple SPI digital interface, with a digital supply that can operate as low as 1.65 V, allows for easy interfacing to a wide variety of digital controllers. Automatic power-down can be enabled when operating at slower speeds to dramatically reduce power consumption.

Offered in a tiny 3-mm × 3-mm WQFN package, the ADS7947, ADS7948, and ADS7949 are fully specified over the extended temperature range of –40°C to +125°C and are suitable for a wide variety of data acquisition applications where high performance, low power, and small size are key.

Device Information⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|-----------|-------------------|
| ADS794x | WQFN (16) | 3.00 mm × 3.00 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

ADS794x Block Diagram

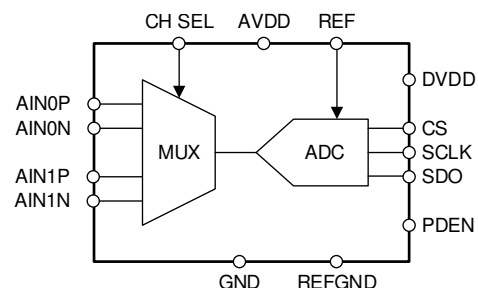


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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Original (September 2010) to Revision A | Page |
|--|------|
| • Added <i>Device Information</i> table, <i>ESD Ratings</i> table, <i>Recommended Operating Conditions</i> table, <i>Switching Characteristics</i> table, <i>Functional Block Diagram</i> section, <i>Feature Description</i> section, <i>Device Functional Modes</i> section, <i>Programming</i> section, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section | 1 |
| • Changed document title | 1 |
| • Changed QFN to WQFN throughout document | 1 |
| • Added <i>High resolution, high throughput</i> : Features bullet | 1 |
| • Changed temperature range Features bullet from <i>Fully Specified</i> from to <i>Extended temperature range</i> | 1 |
| • Changed <i>Description</i> section for clarity and changed <i>ADC with an inherent sample-and-hold (S/H) input stage</i> to <i>ADC</i> | 1 |
| • Changed page 1 figure and added title | 1 |
| • Changed title of <i>Family and Ordering Information</i> to <i>Device Comparison Table</i> | 4 |
| • Changed thermal symbols for $R_{\theta JA}$, $R_{\theta JC(top)}$, $R_{\theta JB}$, and $R_{\theta JC(bot)}$ | 6 |
| • Deleted <i>Full-scale input span</i> , <i>Absolute input range</i> , <i>External Reference</i> , <i>AVDD</i> , and <i>DVDD</i> parameters and <i>Temperature Range</i> section from <i>Electrical Characteristics: ADS7947 (12-Bit)</i> table | 6 |
| • Deleted <i>Full-scale input span</i> , <i>Absolute input range</i> , <i>External Reference</i> , <i>AVDD</i> , and <i>DVDD</i> parameters and <i>Temperature Range</i> section from <i>Electrical Characteristics: ADS7948 (10-Bit)</i> table | 8 |
| • Deleted <i>Full-scale input span</i> , <i>Absolute input range</i> , <i>External Reference</i> , <i>AVDD</i> , and <i>DVDD</i> parameters and <i>Temperature Range</i> section from <i>Electrical Characteristics: ADS7949 (8-Bit)</i> table | 10 |
| • Changed <i>Timing Requirements</i> table: added section titles, moved switching parameters into <i>Switching Characteristics</i> table | 11 |
| • Changed symbol for <i>Pulse duration</i> , <i>SCLK low</i> parameter from t_{W1} to t_{WL} | 11 |
| • Added symbol to <i>SCLK frequency</i> parameter | 11 |
| • Changed title of <i>PCB Layout/Schematic Guidelines</i> to <i>Layout</i> and changed format of section | 31 |

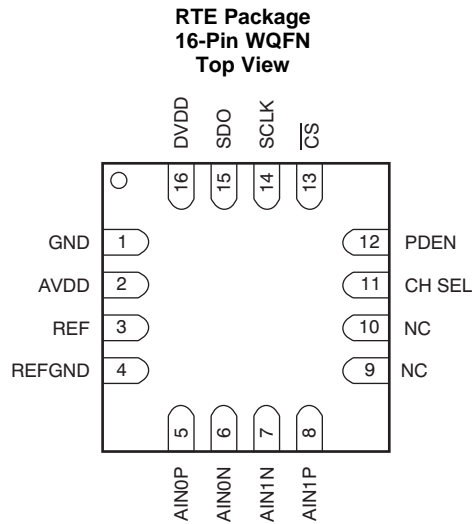
Revision History (continued)

- Changed *Recommended ADC Schematic* figure 31
-

5 Device Comparison Table

| PRODUCT | RESOLUTION (Bits) | INPUT | SAMPLE RATE (MSPS) |
|---------|-------------------|-------------------------------|--------------------|
| ADS7947 | 12 | Unipolar, pseudo-differential | 2 |
| ADS7948 | 10 | Unipolar, pseudo-differential | 2 |
| ADS7949 | 8 | Unipolar, pseudo-differential | 2 |

6 Pin Configuration and Functions



Pin Functions

| PIN NO. | PIN NAME | FUNCTION | DESCRIPTION |
|---------|-----------------|----------------|--|
| 1 | GND | Analog/digital | Power supply ground; all analog and digital signals are referred with respect to this pin. |
| 2 | AVDD | Analog | ADC power supply. |
| 3 | REF | Analog | ADC positive reference input; decouple this pin with REFGND. |
| 4 | REFGND | Analog | Reference return; short to analog ground plane. |
| 5 | AIN0P | Analog input | Positive analog input, channel 0. |
| 6 | AIN0N | Analog input | Negative analog input, channel 0. The allowable signal swing on this pin is $\pm 0.2V$; this pin can be grounded. |
| 7 | AIN1N | Analog input | Negative analog input, channel 1. The allowable signal swing on this pin is $\pm 0.2V$; this pin can be grounded. |
| 8 | AIN1P | Analog input | Positive analog input, channel 1. |
| 9 | NC | — | Not connected internally, TI recommends externally shorting this pin to GND. |
| 10 | NC | — | Not connected internally, TI recommends externally shorting this pin to GND. |
| 11 | CH SEL | Digital input | This pin selects the analog input channel. Low = channel 0, high = channel 1. TI recommends changing the channel within a window of one clock; from half a clock after the \overline{CS} falling edge. This change ensures the settling on the multiplexer output before the sample start. |
| 12 | PDEN | Digital input | This pin enables a power-down feature if this pin is high at the \overline{CS} rising edge. |
| 13 | \overline{CS} | Digital input | Chip-select signal; active low. |
| 14 | SCLK | Digital input | Serial SPI clock. |
| 15 | SDO | Digital output | Serial data out. |
| 16 | DVDD | Digital | Digital I/O supply. |

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | MIN | MAX | UNIT |
|------------------------------|---------------------------|------|------------|------|
| AINxP to GND or AINxN to GND | | -0.3 | AVDD + 0.3 | V |
| AVDD to GND or DVDD to GND | | -0.3 | 7 | V |
| Digital input voltage to GND | | -0.3 | DVDD + 0.3 | V |
| Digital output to GND | | -0.3 | DVDD + 0.3 | V |
| Temperature | Operating | -40 | 125 | °C |
| | Storage, T _{stg} | -65 | 150 | °C |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 ESD Ratings

| | | | VALUE | UNIT |
|--------------------|-------------------------|--|-------|------|
| V _(ESD) | Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾ | ±2000 | V |
| | | Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾ | ±500 | |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions: ADS794x (12-, 10-, 8-Bit)

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | MIN | NOM | MAX | UNIT |
|---|--------------------------------------|---------------|-----|------------------|------|
| POWER SUPPLY | | | | | |
| AVDD | Analog supply voltage | 2.7 | 3.3 | 5.5 | V |
| DVDD | Digital supply voltage | 1.65 | 3.3 | AVDD | V |
| REFERENCE INPUT | | | | | |
| V _{REF} | External reference input | 2.5 | | AVDD | V |
| ANALOG INPUTS | | | | | |
| FSR | Full-scale input span ⁽¹⁾ | AINxP – AINxN | | V _{REF} | V |
| V _{IN} | Absolute input range | AIN0P, AIN1P | | AVDD + 0.2 | V |
| | | AIN0N, AIN1M | | 0.2 | |
| TEMPERATURE RANGE | | | | | |
| Temperature range for specified performance | | -40 | | 125 | °C |

- (1) Ideal input span; does not include gain or offset error.

7.4 Thermal Information

| THERMAL METRIC ⁽¹⁾ | | ADS794x | UNIT |
|-------------------------------|--|------------|------|
| | | RTE (WQFN) | |
| | | 16 PINS | |
| R _{θJA} | Junction-to-ambient thermal resistance | 54.3 | °C/W |
| R _{θJC(top)} | Junction-to-case (top) thermal resistance | 53.7 | °C/W |
| R _{θJB} | Junction-to-board thermal resistance | 19.2 | °C/W |
| ψ _{JT} | Junction-to-top characterization parameter | 0.3 | °C/W |
| ψ _{JB} | Junction-to-board characterization parameter | 14.5 | °C/W |
| R _{θJC(bot)} | Junction-to-case (bottom) thermal resistance | 5.2 | °C/W |

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics application report](#).

7.5 Electrical Characteristics: ADS7947 (12-Bit)

minimum and maximum values at AVDD = 2.7 V to 5.5 V, DVDD = 1.65 V to AVDD, T_A = –40°C to +125°C, and f_{SAMPLE} = 2 MSPS (unless otherwise noted); typical values at AVDD = 3 V, DVDD = 1.8 V, T_A = +25°C, and f_{SAMPLE} = 2 MSPS

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|---|-----|-------|------|--------------------|
| ANALOG INPUT | | | | | |
| Input capacitance ⁽¹⁾ | | | 32 | | pF |
| Input leakage current | At +125°C | | 1.5 | | nA |
| SYSTEM PERFORMANCE | | | | | |
| Resolution | | | 12 | | Bits |
| No missing codes | | 12 | | | Bits |
| Integral linearity | | –1 | ±0.3 | 1 | LSB ⁽²⁾ |
| Differential linearity | | –1 | ±0.3 | 1 | LSB |
| Offset error ⁽³⁾ | | –1 | ±0.3 | 1 | LSB |
| Gain error | | –1 | ±0.3 | 1 | LSB |
| Transition noise | | | | 25 | μV _{RMS} |
| Power-supply rejection | | | 60 | | dB |
| SAMPLING DYNAMICS | | | | | |
| Conversion time | | | | 13.5 | SCLK |
| Acquisition time | | 80 | | | ns |
| Maximum sample rate (throughput rate) | 34-MHz SCLK with a 16-clock frame | | | 2 | MSPS |
| | 34-MHz SCLK and \overline{CS} low for 13.5 clocks | | | 2.1 | MSPS |
| Aperture delay | | | | 5 | ns |
| Aperture jitter | | | 10 | | ps |
| Step response | | | 80 | | ns |
| Overshoot recovery | | | 80 | | ns |
| DYNAMIC CHARACTERISTICS | | | | | |
| Total harmonic distortion (THD) ⁽⁴⁾ | 100kHz | | –85 | | dB |
| Signal-to-noise ratio (SNR) | 100 kHz | 72 | 73 | | dB |
| Signal-to-noise and distortion ratio (SINAD) | 100 kHz | | 72.75 | | dB |
| Spurious-free dynamic range (SFDR) | 100 kHz | | 86 | | dB |
| Full-power bandwidth | At –3 dB | | 15 | | MHz |
| DIGITAL INPUT/OUTPUT | | | | | |
| Logic family | CMOS | | | | |

(1) See [Figure 40](#) for sampling circuit details.

(2) LSB means least significant bit.

(3) Measured relative to an ideal full-scale input.

(4) Calculated on the first nine harmonics of the input frequency.

Electrical Characteristics: ADS7947 (12-Bit) (continued)

minimum and maximum values at AVDD = 2.7 V to 5.5 V, DVDD = 1.65 V to AVDD, T_A = –40°C to +125°C, and f_{SAMPLE} = 2 MSPS (unless otherwise noted); typical values at AVDD = 3 V, DVDD = 1.8 V, T_A = +25°C, and f_{SAMPLE} = 2 MSPS

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------------------------------|-----------------------------------|---|------------|-----|---------|------|
| Logic level | V _{IH} | | 0.7DVDD | | | V |
| | V _{IL} | | | | 0.3DVDD | V |
| | V _{OH} | I _{SOURCE} = 200 μA | DVDD – 0.2 | | | V |
| | V _{OL} | I _{SINK} = 200 μA | 0.4 | | | V |
| Input leakage current | I _{IH} , I _{IL} | 0 < V _{IN} < DVDD | | ±20 | | nA |
| POWER-SUPPLY REQUIREMENTS | | | | | | |
| AVDD supply current | I _{DYNAMIC} | AVDD = 3.3 V, f _{SAMPLE} = 2 MSPS | | 2.5 | | mA |
| | | AVDD = 5 V, f _{SAMPLE} = 2 MSPS | | 3 | 3.5 | mA |
| | I _{STATIC} | AVDD = 3.3 V, SCLK off | | 1.8 | | mA |
| | | AVDD = 5 V, SCLK off | | 1.9 | 2.5 | mA |
| DVDD supply current ⁽⁵⁾ | | DVDD = 3.3 V, SCLK = 34 MHz, SDO load 20 pF | | 500 | | μA |
| Power-down state AVDD supply current | I _{PD-DYNAMIC} | SCLK = 34 MHz | | | 550 | μA |
| | I _{PD-STATIC} | SCLK off | | | 2.5 | μA |
| Power-up time | | | | | 1 | μs |

(5) DVDD consumes only dynamic current. I_{DVDD} = C_{LOAD} × DVDD × number of 0→1 transitions in SDO × f_{SAMPLE}. This current is load-dependent and there is no DVDD current when the output is not toggling.

7.6 Electrical Characteristics: ADS7948 (10-Bit)

minimum and maximum values at AVDD = 2.7 V to 5.5 V, DVDD = 1.65 V to AVDD, T_A = –40°C to +125°C, and f_{SAMPLE} = 2 MSPS (unless otherwise noted); typical values at AVDD = 3 V, DVDD = 1.8 V, T_A = +25°C, and f_{SAMPLE} = 2 MSPS

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|-----------------|---|----------------------------|---------|------|--------------------|
| ANALOG INPUT | | | | | | |
| Input capacitance ⁽¹⁾ | | | | 32 | | pF |
| Input leakage current | | At +125°C | | 1.5 | | nA |
| SYSTEM PERFORMANCE | | | | | | |
| Resolution | | | | 10 | | Bits |
| No missing codes | | | 10 | | | Bits |
| Integral linearity | | | –0.5 | ±0.15 | 0.5 | LSB ⁽²⁾ |
| Differential linearity | | | –0.5 | ±0.15 | 0.5 | LSB |
| Offset error ⁽³⁾ | | | –0.5 | ±0.15 | 0.5 | LSB |
| Gain error | | | –0.5 | ±0.15 | 0.5 | LSB |
| Transition noise | | | | | 25 | μV _{RMS} |
| Power-supply rejection | | | | 60 | | dB |
| SAMPLING DYNAMICS | | | | | | |
| Conversion time | | | | | 10.5 | SCLK |
| Acquisition time | | | 80 | | | ns |
| Maximum sample rate (throughput rate) | | 34-MHz SCLK in 16-clock frame | | | 2 | MSPS |
| | | 34-MHz SCLK and \overline{CS} low for 10.5 clocks | | | 2.57 | MSPS |
| Aperture delay | | | | | 5 | ns |
| Aperture jitter | | | | 10 | | ps |
| Step response | | | | 80 | | ns |
| Overvoltage recovery | | | | 80 | | ns |
| DYNAMIC CHARACTERISTICS | | | | | | |
| Total harmonic distortion (THD) ⁽⁴⁾ | | 100kHz | | –80 | | dB |
| Signal-to-noise ratio (SNR) | | 100 kHz | 61 | | | dB |
| Signal-to-noise and distortion ratio (SINAD) | | 100 kHz | | 61 | | dB |
| Spurious-free dynamic range (SFDR) | | 100 kHz | | 81 | | dB |
| Full-power bandwidth | | At –3 dB | | 15 | | MHz |
| DIGITAL INPUT/OUTPUT | | | | | | |
| Logic family | | CMOS | | | | |
| Logic level | V _{IH} | | 0.7DVDD | | | V |
| | V _{IL} | | | 0.3DVDD | | V |
| | V _{OH} | I _{SOURCE} = 200 μA | DVDD – 0.2 | | | V |
| | V _{OL} | I _{SINK} = 200 μA | 0.4 | | | V |
| Input leakage current | | I _{IH} , I _{IL} | 0 < V _{IN} < DVDD | | ±20 | nA |

(1) See [Figure 40](#) for sampling circuit details.

(2) LSB means least significant bit.

(3) Measured relative to an ideal full-scale input.

(4) Calculated on the first nine harmonics of the input frequency.

Electrical Characteristics: ADS7948 (10-Bit) (continued)

minimum and maximum values at AVDD = 2.7 V to 5.5 V, DVDD = 1.65 V to AVDD, $T_A = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, and $f_{\text{SAMPLE}} = 2$ MSPS (unless otherwise noted); typical values at AVDD = 3 V, DVDD = 1.8 V, $T_A = +25^{\circ}\text{C}$, and $f_{\text{SAMPLE}} = 2$ MSPS

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------------------------------|-------------------------|---|-----|-----|-----|------|
| POWER-SUPPLY REQUIREMENTS | | | | | | |
| AVDD supply current | I _{DYNAMIC} | AVDD = 3.3 V, $f_{\text{SAMPLE}} = 2$ MSPS | | 2.5 | | mA |
| | | AVDD = 5 V, $f_{\text{SAMPLE}} = 2$ MSPS | | 3 | 3.5 | mA |
| | I _{STATIC} | AVDD = 3.3 V, SCLK off | | 1.8 | | mA |
| | | AVDD = 5 V, SCLK off | | 1.9 | 2.5 | mA |
| DVDD supply current ⁽⁵⁾ | | DVDD = 3.3 V, SCLK = 34 MHz, SDO load 20 pF | | 500 | | μA |
| Power-down state AVDD supply current | I _{PD-DYNAMIC} | SCLK = 34 MHz | | | 550 | μA |
| | I _{PD-STATIC} | SCLK off | | | 2.5 | μA |
| Power-up time | | | | | 1 | μs |

(5) DVDD consumes only dynamic current. $I_{\text{DVDD}} = C_{\text{LOAD}} \times \text{DVDD} \times \text{number of } 0 \rightarrow 1 \text{ transitions in SDO} \times f_{\text{SAMPLE}}$. This current is load-dependent and there is no DVDD current when the output is not toggling.

7.7 Electrical Characteristics: ADS7949 (8-Bit)

minimum and maximum values at AVDD = 2.7 V to 5.5 V, DVDD = 1.65 V to AVDD, TA = –40°C to +125°C, and fSAMPLE = 2 MSPS (unless otherwise noted); typical values at AVDD = 3 V, DVDD = 1.8 V, TA = +25°C, and fSAMPLE = 2 MSPS

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|-----------------|--|----------------------------|---------|-----|--------------------|
| ANALOG INPUT | | | | | | |
| Input capacitance ⁽¹⁾ | | | | 32 | | pF |
| Input leakage current | | At +125°C | | 1.5 | | nA |
| SYSTEM PERFORMANCE | | | | | | |
| Resolution | | | | 8 | | Bits |
| No missing codes | | | 8 | | | Bits |
| Integral linearity | | | –0.3 | ±0.06 | 0.3 | LSB ⁽²⁾ |
| Differential linearity | | | –0.3 | ±0.06 | 0.3 | LSB |
| Offset error ⁽³⁾ | | | –0.3 | ±0.06 | 0.3 | LSB |
| Gain error | | | –0.3 | ±0.06 | 0.3 | LSB |
| Transition noise | | | | | 25 | μVRMS |
| Power-supply rejection | | | | 60 | | dB |
| SAMPLING DYNAMICS | | | | | | |
| Conversion time | | | | | 8.5 | SCLK |
| Acquisition time | | | 80 | | | ns |
| Maximum sample rate (throughput rate) | | 34-MHz SCLK in 16-clock frame | | | 2 | MSPS |
| | | 34-MHz SCLK and \overline{CS} low for 8.5 clocks | | | 3 | MSPS |
| Aperture delay | | | | | 5 | ns |
| Aperture jitter | | | | 10 | | ps |
| Step response | | | | 80 | | ns |
| Overvoltage recovery | | | | 80 | | ns |
| DYNAMIC CHARACTERISTICS | | | | | | |
| Total harmonic distortion (THD) ⁽⁴⁾ | | 100 kHz | | –80 | | dB |
| Signal-to-noise ratio (SNR) | | 100 kHz | 49 | | | dB |
| Signal-to-noise and distortion ratio (SINAD) | | 100 kHz | | 49 | | dB |
| Spurious-free dynamic range (SFDR) | | 100 kHz | | 81 | | dB |
| Full-power bandwidth | | At –3 dB | | 15 | | MHz |
| DIGITAL INPUT/OUTPUT | | | | | | |
| Logic family | | CMOS | | | | |
| Logic level | V _{IH} | | 0.7DVDD | | | V |
| | V _{IL} | | | 0.3DVDD | | V |
| | V _{OH} | I _{SOURCE} = 200 μA | DVDD – 0.2 | | | V |
| | V _{OL} | I _{SINK} = 200 μA | 0.4 | | | V |
| Input leakage current | | I _{IH} , I _{IL} | 0 < V _{IN} < DVDD | | ±20 | nA |

(1) See Figure 40 for sampling circuit details.

(2) LSB means least significant bit.

(3) Measured relative to an ideal full-scale input.

(4) Calculated on the first nine harmonics of the input frequency.

Electrical Characteristics: ADS7949 (8-Bit) (continued)

minimum and maximum values at AVDD = 2.7 V to 5.5 V, DVDD = 1.65 V to AVDD, T_A = –40°C to +125°C, and f_{SAMPLE} = 2 MSPS (unless otherwise noted); typical values at AVDD = 3 V, DVDD = 1.8 V, T_A = +25°C, and f_{SAMPLE} = 2 MSPS

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------------------------------|-------------------------|---|-----|-----|-----|------|
| POWER-SUPPLY REQUIREMENTS | | | | | | |
| AVDD supply current | I _{DYNAMIC} | AVDD = 3.3 V, f _{SAMPLE} = 2 MSPS | | 2.5 | | mA |
| | | AVDD = 5 V, f _{SAMPLE} = 2 MSPS | | 3 | 3.5 | mA |
| | I _{STATIC} | AVDD = 3.3 V, SCLK off | | 1.8 | | mA |
| | | AVDD = 5 V, SCLK off | | 1.9 | 2.5 | mA |
| DVDD supply current ⁽⁵⁾ | | DVDD = 3.3 V, SCLK = 34 MHz, SDO load 20 pF | | 500 | | μA |
| Power-down state AVDD supply current | I _{PD-DYNAMIC} | SCLK = 34 MHz | | | 550 | μA |
| | I _{PD-STATIC} | SCLK off | | | 2.5 | μA |
| Power-up time | | | | | 1 | μs |

(5) DVDD consumes only dynamic current. I_{DVDD} = C_{LOAD} × DVDD × number of 0→1 transitions in SDO × f_{SAMPLE}. This current is load-dependent and there is no DVDD current when the output is not toggling.

7.8 Timing Requirements

at DVDD⁽¹⁾ = 1.65 V to AVDD (unless otherwise noted); minimum and maximum values at T_A = –40°C to +125°C, typical values at T_A = 25°C

| | | | MIN | NOM | MAX | UNIT |
|------------------------------|---|---------------------------------|-----|-----|------|------|
| CONVERSION CYCLE | | | | | | |
| f _{SAMPLE} | Sample rate (throughput rate) | SCLK = 34 MHz, 16 clock frame | | | 2 | MSPS |
| | f _{SAMPLE MAX} = 1 / (t _{CONV MAX} + t _{ACQ MIN}) | ADS7947 (12 bit), SCLK = 34 MHz | | | 2.1 | MSPS |
| | | ADS7948 (10 bit), SCLK = 34 MHz | | | 2.57 | |
| | | ADS7949 (8 bit), SCLK = 34 MHz | | | 3 | |
| t _{ACQ} | Acquisition time | | 80 | | | ns |
| POWER DOWN | | | | | | |
| t _{PDSU} | Setup time, PDEN high to \overline{CS} rising edge (see Figure 45 and Figure 46) | | 2 | | | ns |
| t _{PDH} | Hold time, \overline{CS} rising edge to PDEN falling edge (see Figure 45) | | 20 | | | ns |
| SPI INTERFACE TIMINGS | | | | | | |
| t _{W1} | Pulse duration, \overline{CS} high | | 25 | | | ns |
| t _{SU1} | Setup time, \overline{CS} low to first rising edge of SCLK | DVDD = 1.8 V | 3.5 | | | ns |
| | | DVDD = 3 V | 3.5 | | | |
| | | DVDD = 5 V | 3.5 | | | |
| t _{D4} | Delay time, \overline{CS} rising edge from conversion end (see the t _{CONV} specification for conversion time) | | 10 | | | ns |
| t _{WH} | Pulse duration, SCLK high | | 11 | | | ns |
| t _{WL} | Pulse duration, SCLK low | | 11 | | | ns |
| f _{SCLK} | SCLK frequency | | 0.4 | 34 | 40 | MHz |

(1) 1.8-V specifications apply from 1.65 V to 2 V; 3-V specifications apply from 2.7 V to 3.6 V; 5-V specifications apply from 4.75 V to 5.25 V.

7.9 Switching Characteristics

at DVDD = 1.65 V to AVDD (unless otherwise noted); minimum and maximum values at T_A = -40°C to +125°C, typical values at T_A = 25°C

| PARAMETER | | TEST CONDITIONS ⁽¹⁾ | MIN | TYP | MAX | UNIT |
|--------------------------------|---|--------------------------------|-----|-----|------|------|
| t _{CONV} | Conversion time | ADS7947 (12 bit) | | | 13.5 | SCLK |
| | | ADS7948 (10 bit) | | | 10.5 | |
| | | ADS7949 (8 bit) | | | 8.5 | |
| t _{D1} | Delay time, \overline{CS} low to first data (D0-15) out | DVDD = 1.8 V | | | 14.5 | ns |
| | | DVDD = 3 V | | | 12.5 | |
| | | DVDD = 5 V | | | 8.5 | |
| t _{D2} ⁽²⁾ | Delay time, SCLK falling to SDO | DVDD = 1.8 V | | | 11 | ns |
| | | DVDD = 3 V | | | 9 | |
| | | DVDD = 5 V | | | 7.1 | |
| t _{H1} | Hold time, SCLK falling to data valid | DVDD = 1.8 V | 4 | | | ns |
| | | DVDD = 3 V | 3 | | | |
| | | DVDD = 5 V | 2 | | | |
| t _{D3} | Delay time, \overline{CS} high to SDO 3-state | DVDD = 1.8 V | | | 15 | ns |
| | | DVDD = 3 V | | | 12.5 | |
| | | DVDD = 5 V | | | 8.5 | |

(1) 1.8-V specifications apply from 1.65 V to 2 V; 3-V specifications apply from 2.7 V to 3.6 V; 5-V specifications apply from 4.75 V to 5.25 V.

(2) With 50-pF load.

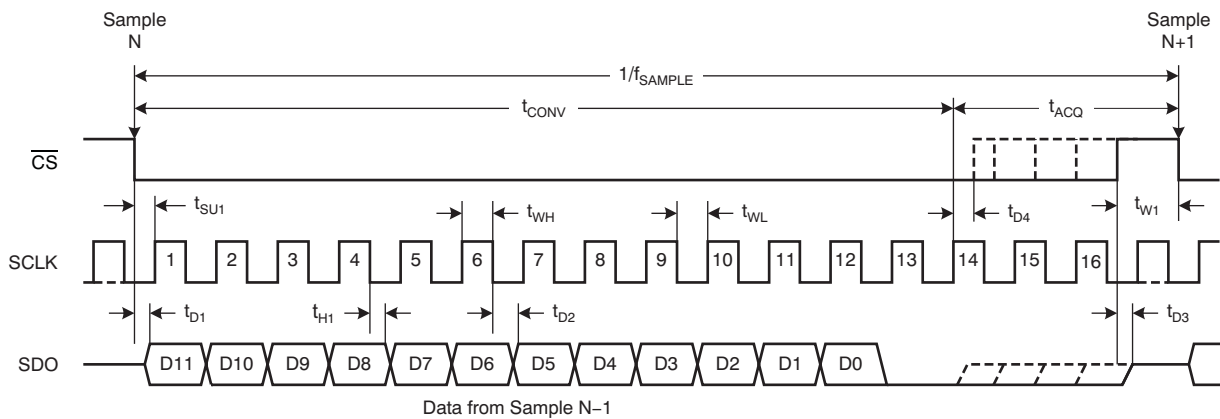
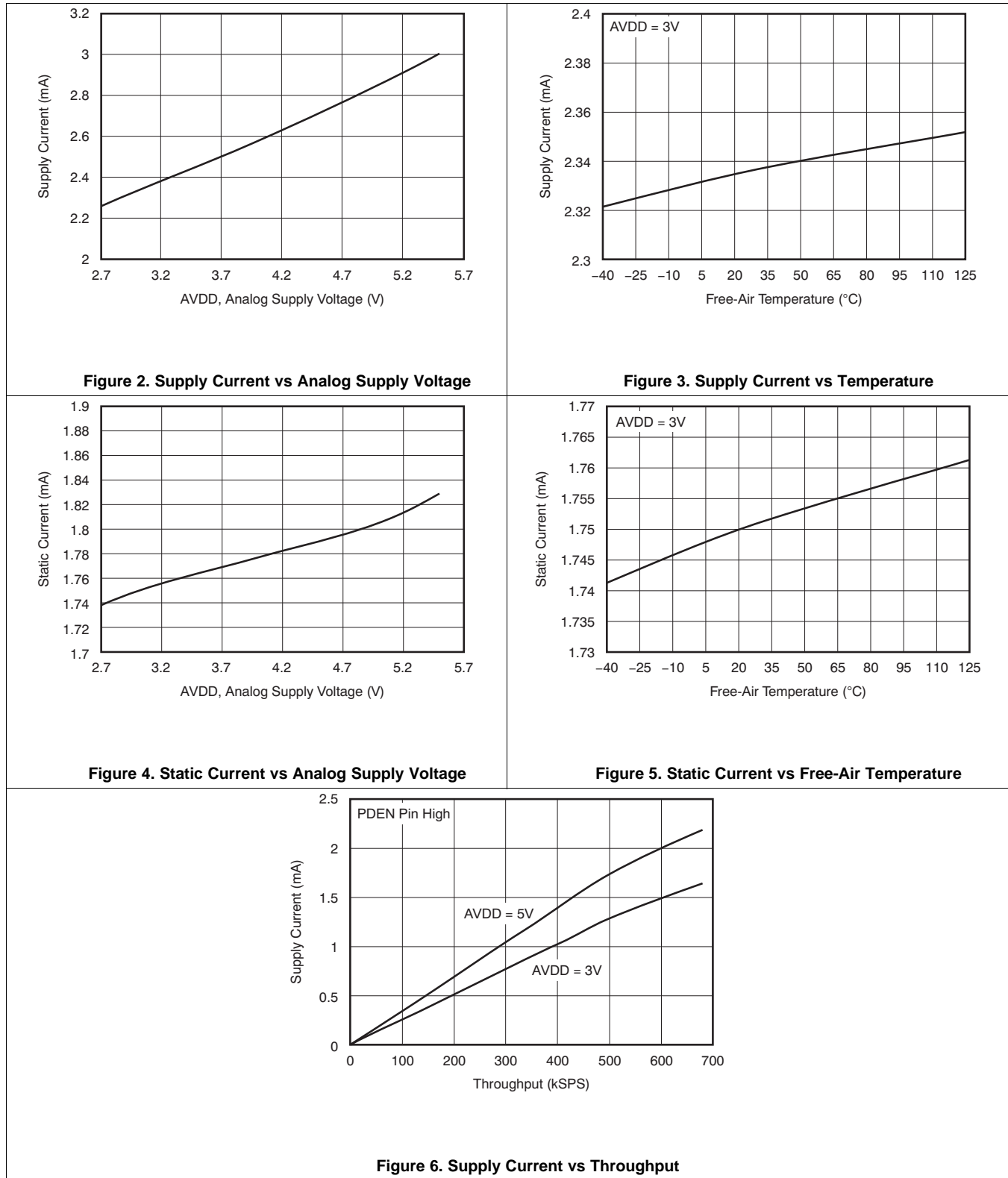


Figure 1. Timing Diagram

7.10 Typical Characteristics: ADS7947, ADS7948, ADS7949

at $T_A = 25^\circ\text{C}$, $DVDD = 1.8\text{ V}$, $V_{REF} = 2.5\text{ V}$, and $f_{SAMPLE} = 2\text{ MSPS}$ (unless otherwise noted)



7.11 Typical Characteristics: ADS7947 (12-Bit)

At $T_A = 25^\circ\text{C}$, $DVDD = 1.8\text{ V}$, $V_{REF} = 2.5\text{ V}$, and $f_{SAMPLE} = 2\text{ MSPS}$ (unless otherwise noted)

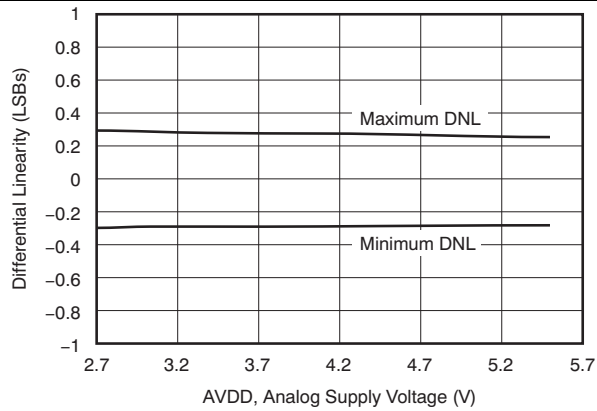


Figure 7. Differential Linearity vs Analog Supply Voltage

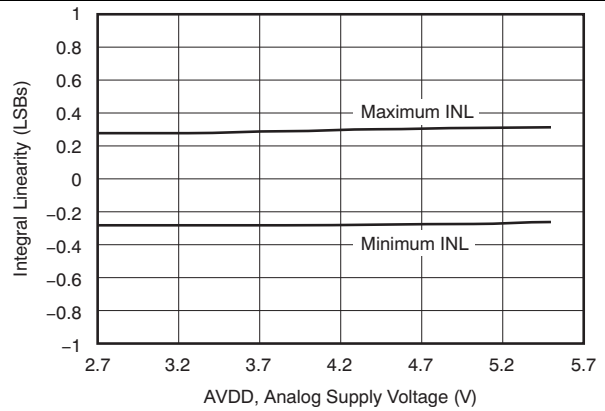


Figure 8. Integral Linearity vs Analog Supply Voltage

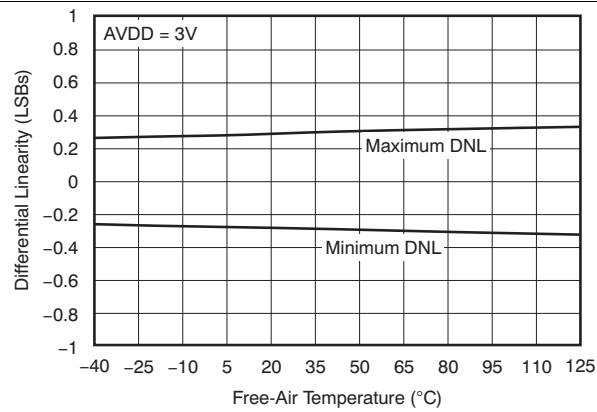


Figure 9. Differential Linearity vs Temperature

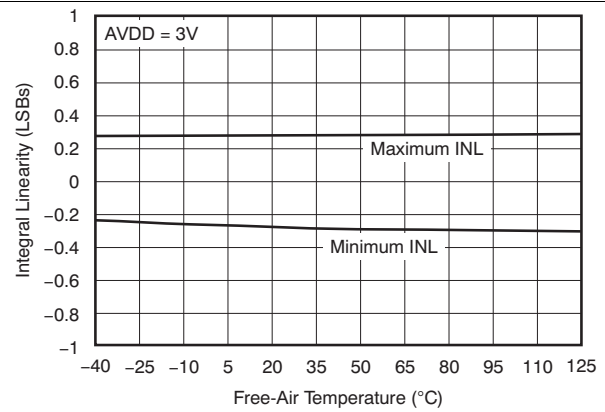


Figure 10. Integral Linearity vs Temperature

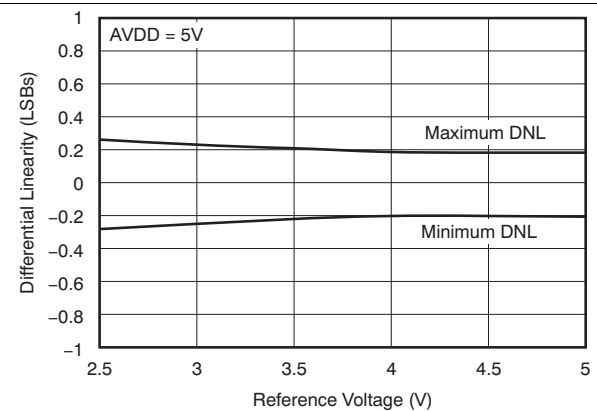


Figure 11. Differential Linearity vs Reference Voltage

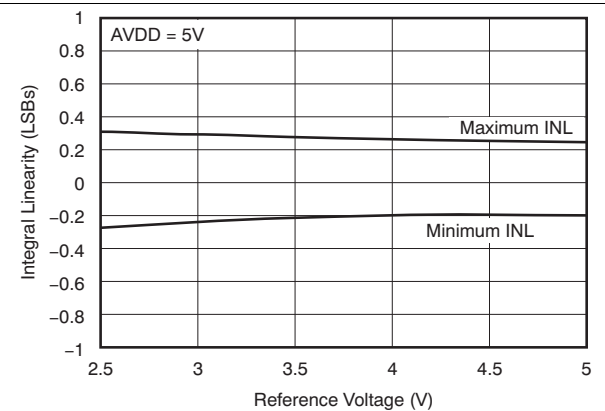


Figure 12. Integral Linearity vs Reference Voltage

Typical Characteristics: ADS7947 (12-Bit) (continued)

At $T_A = 25^\circ\text{C}$, $DVDD = 1.8\text{ V}$, $V_{REF} = 2.5\text{ V}$, and $f_{SAMPLE} = 2\text{ MSPS}$ (unless otherwise noted)

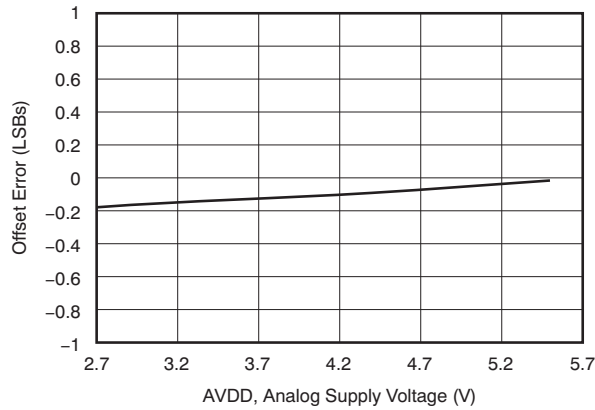


Figure 13. Offset Error vs Analog Supply Voltage

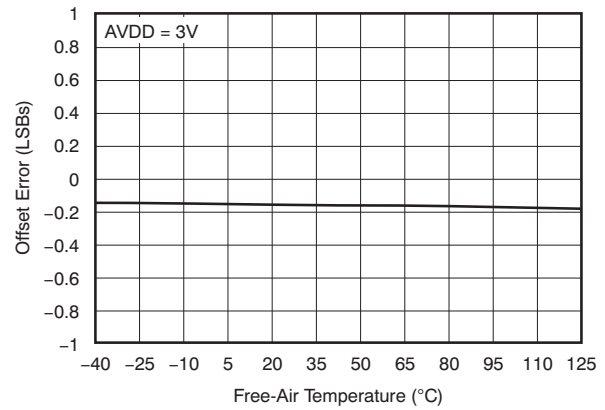


Figure 14. Offset Error vs Temperature

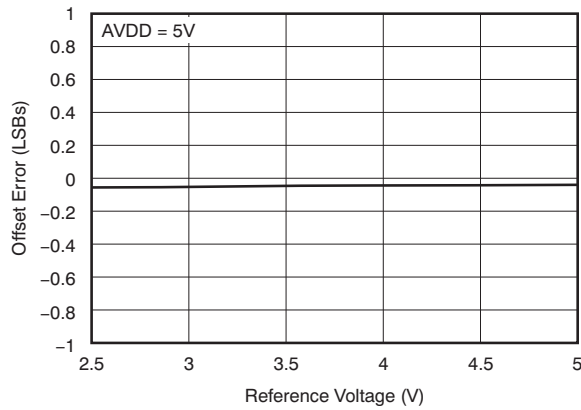


Figure 15. Offset Error vs Reference Voltage

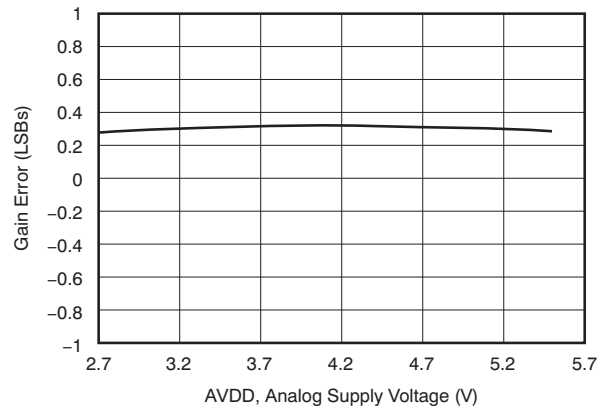


Figure 16. Gain Error vs Analog Supply Voltage

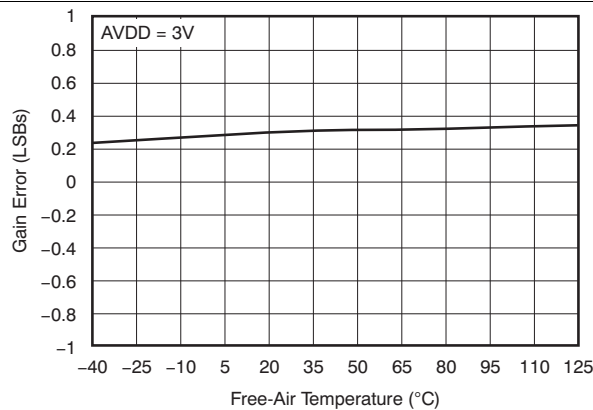


Figure 17. Gain Error vs Temperature

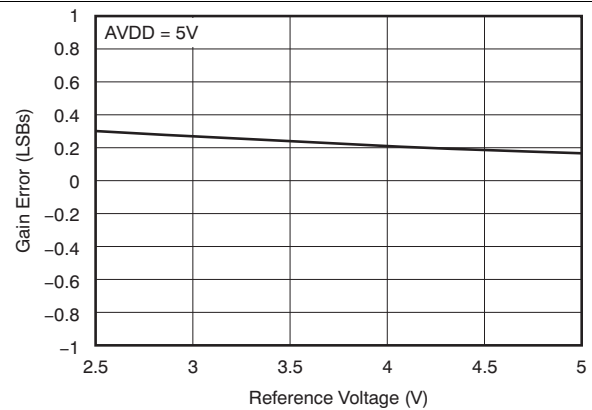


Figure 18. Gain Error vs Reference Voltage

Typical Characteristics: ADS7947 (12-Bit) (continued)

At $T_A = 25^\circ\text{C}$, $DVDD = 1.8\text{ V}$, $V_{REF} = 2.5\text{ V}$, and $f_{SAMPLE} = 2\text{ MSPS}$ (unless otherwise noted)

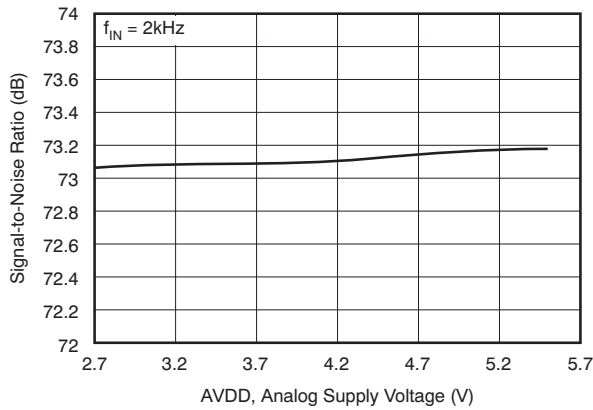


Figure 19. SNR vs Analog Supply Voltage

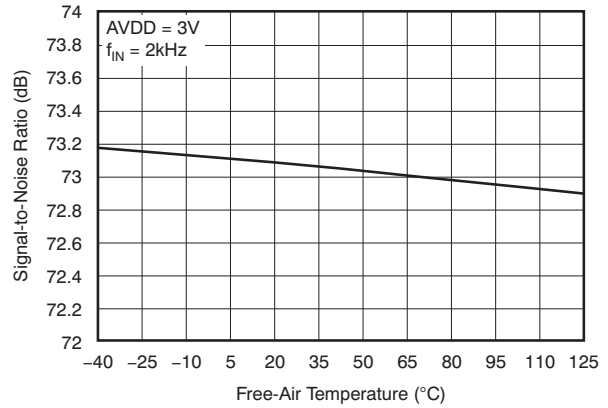


Figure 20. SNR vs Temperature

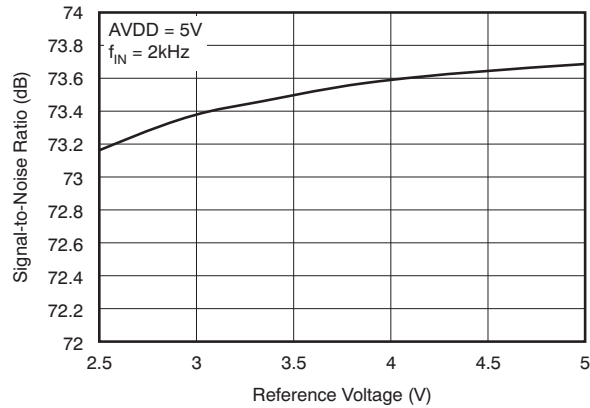


Figure 21. SNR vs Reference Voltage

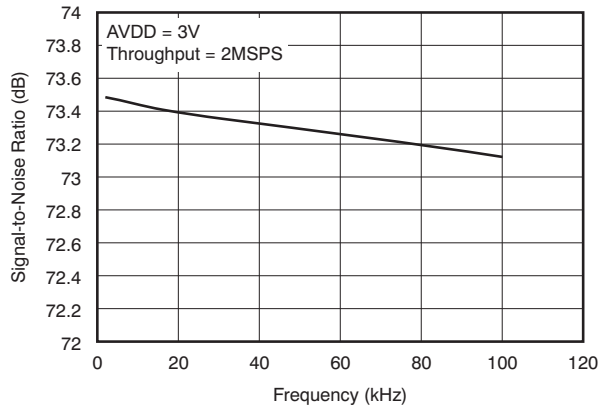


Figure 22. SNR vs Input Frequency

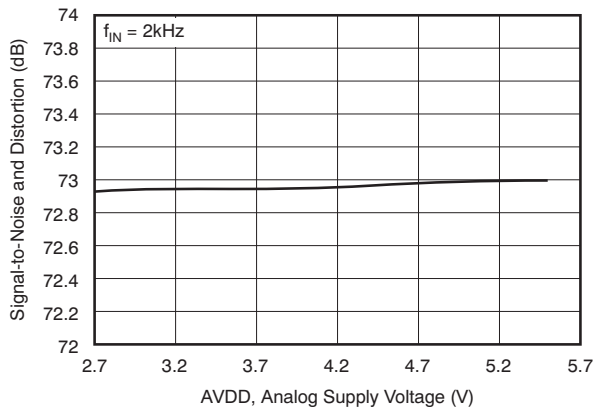


Figure 23. SINAD vs Analog Supply Voltage

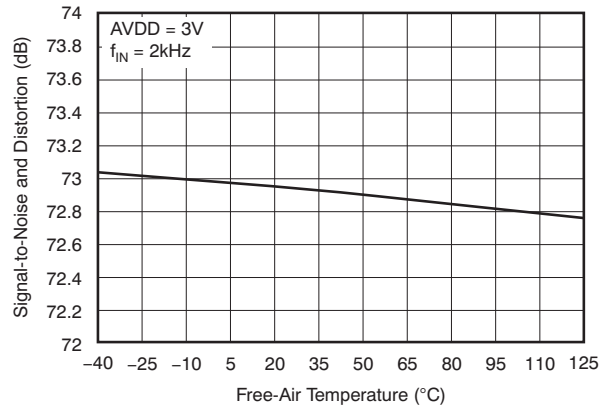


Figure 24. SINAD vs Temperature

Typical Characteristics: ADS7947 (12-Bit) (continued)

At $T_A = 25^\circ\text{C}$, $DVDD = 1.8\text{ V}$, $V_{REF} = 2.5\text{ V}$, and $f_{SAMPLE} = 2\text{ MSPS}$ (unless otherwise noted)

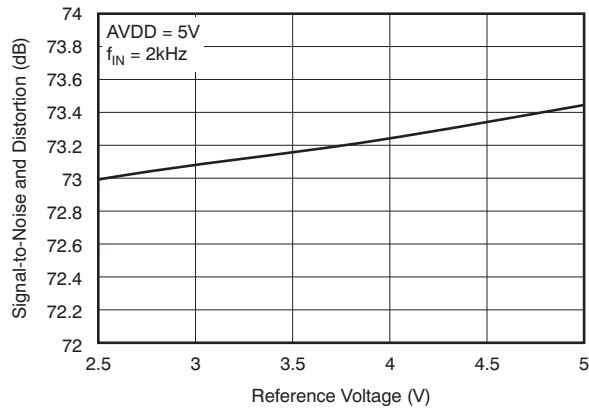


Figure 25. SINAD vs Reference Voltage

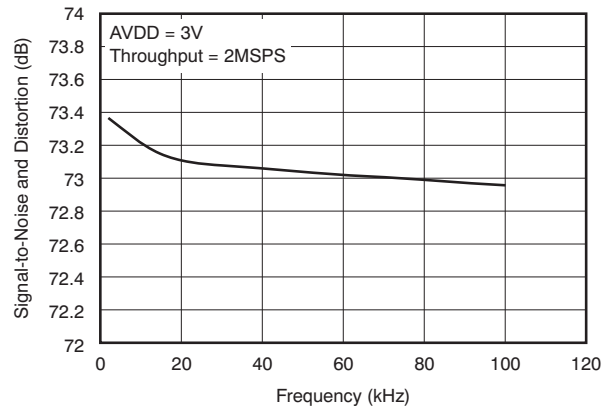


Figure 26. SINAD vs Input Frequency

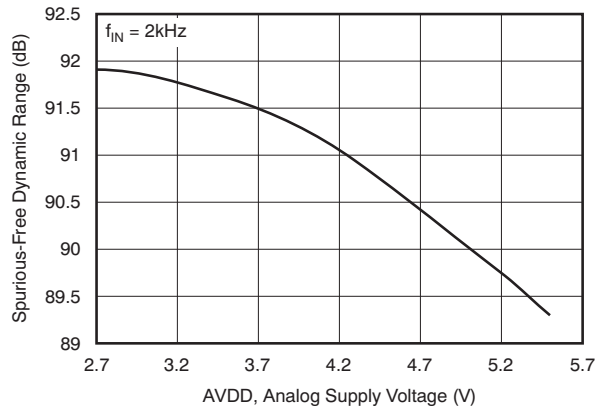


Figure 27. SFDR vs AVDD

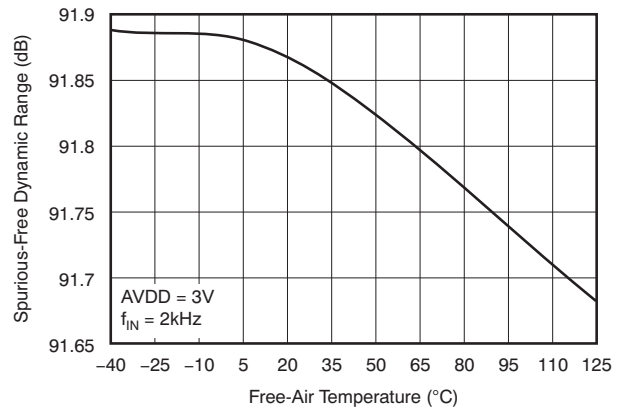


Figure 28. SFDR vs Temperature

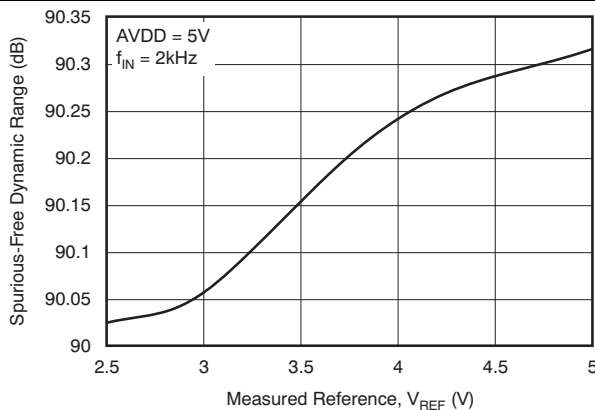


Figure 29. SFDR vs Reference Voltage

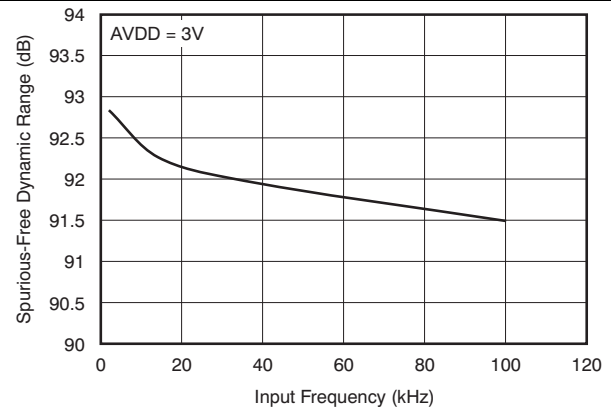


Figure 30. SFDR vs Input Frequency

Typical Characteristics: ADS7947 (12-Bit) (continued)

At $T_A = 25^\circ\text{C}$, $DVDD = 1.8\text{ V}$, $V_{REF} = 2.5\text{ V}$, and $f_{SAMPLE} = 2\text{ MSPS}$ (unless otherwise noted)

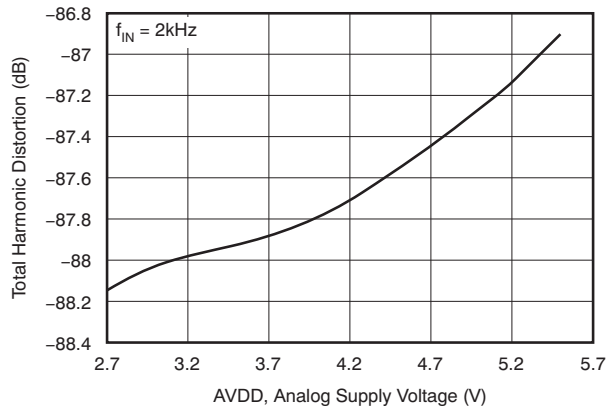


Figure 31. SFDR vs AVDD

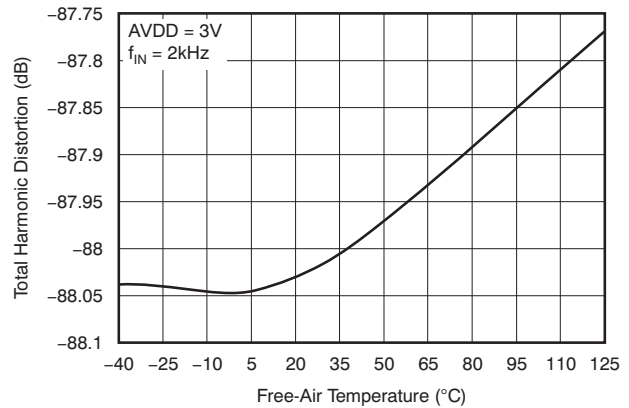


Figure 32. SFDR vs Temperature

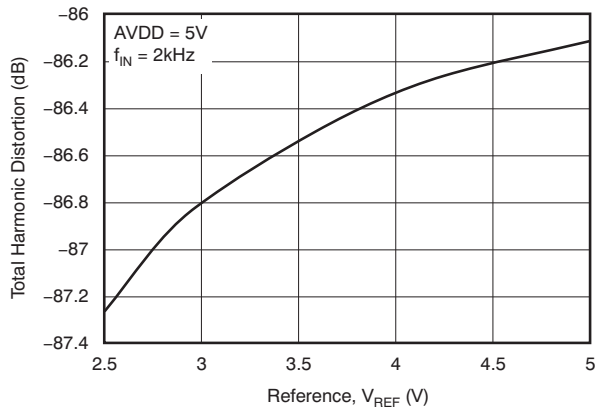


Figure 33. THD vs Reference Voltage

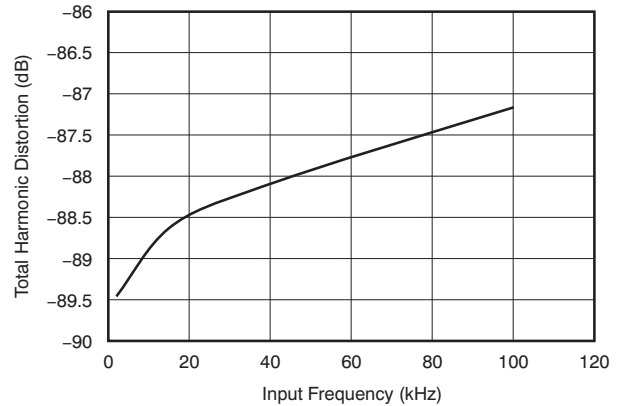


Figure 34. THD vs Input Frequency

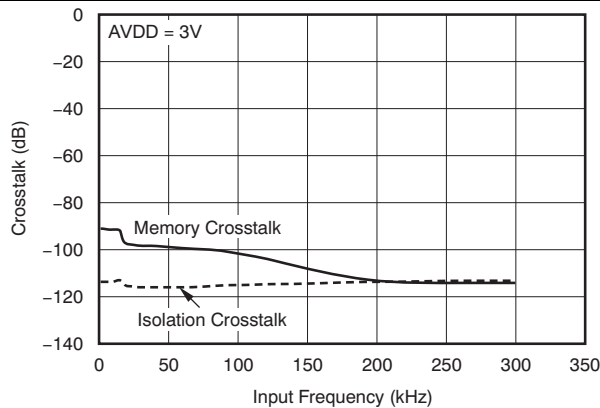


Figure 35. Crosstalk vs Input Frequency

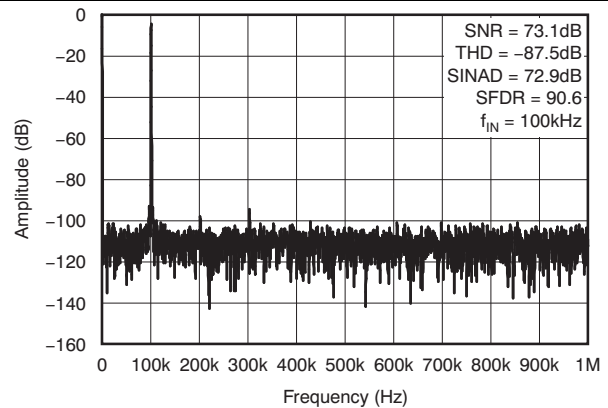
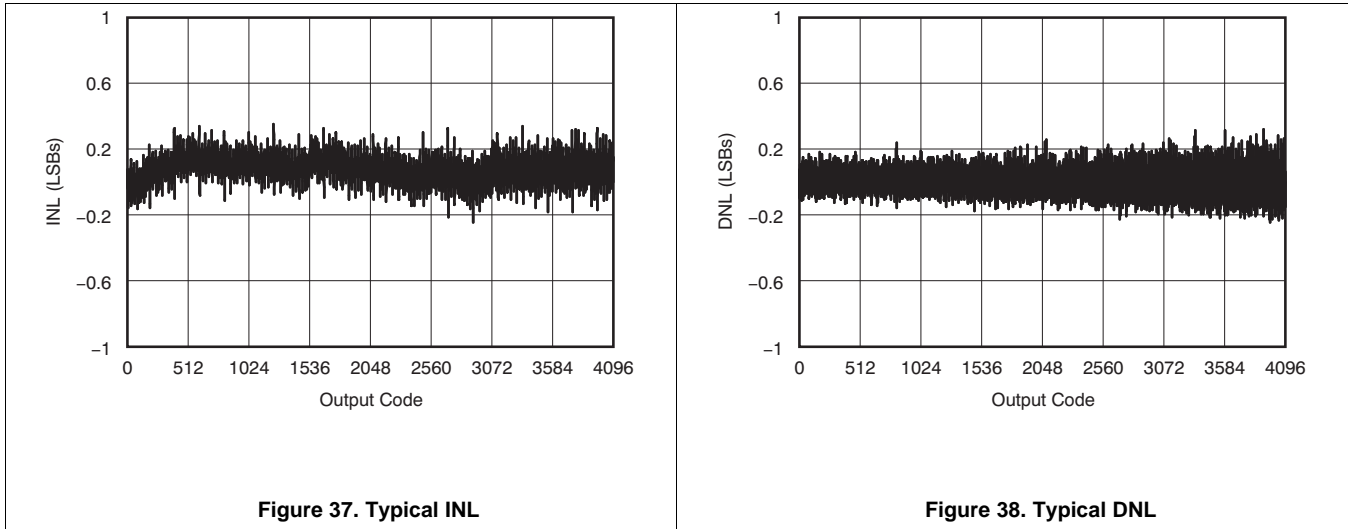


Figure 36. Spectral Response (8192-Point FFT)

Memory crosstalk is the effect of the last converted channel on the current converted channel data. Isolation crosstalk is the effect on the channel being converted that is coming from the signal on the channel that is off.

Typical Characteristics: ADS7947 (12-Bit) (continued)

At $T_A = 25^\circ\text{C}$, $DVDD = 1.8\text{ V}$, $V_{REF} = 2.5\text{ V}$, and $f_{SAMPLE} = 2\text{ MSPS}$ (unless otherwise noted)

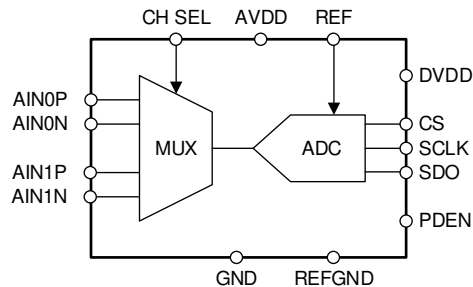


8 Detailed Description

8.1 Overview

The ADS7947 is 12-bit, miniature, dual-channel, low-power successive-approximation register (SAR) analog-to-digital converter (ADC). The ADS7948 and ADS7949 are 10-bit and 8-bit devices, respectively, from the same product family. These devices feature low-power consumption at full-speed. The PDEN pin enables an auto power-down mode that further reduces power consumption at lower speeds.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Multiplexer and ADC Input

The devices feature pseudo-differential inputs with a double-pole, double-throw multiplexer. The negative inputs (AINxN) can accept swings of ± 0.2 V; the positive inputs (AINxP) allow signals in the range of 0 V to V_{REF} over the negative input. The ADC converts the difference in voltage: $V_{AINxP} - V_{AINxN}$. This feature can be used in multiple ways.

Two signals can be connected from different sensors with unequal ground potentials (within ± 0.2 V) to a single ADC. The pseudo-differential ADC rejects common-mode offset and noise. This feature also allows the use of a single-supply op amp. The signal and the AINxN input can be offset by +0.2 V, which provides the ground clearance needed for a single-supply op amp.

Feature Description (continued)

Figure 39 shows the electrostatic discharge (ESD) diodes to supply and ground at every analog input. Make sure that these diodes do not turn on by keeping the supply voltage within the specified input range.

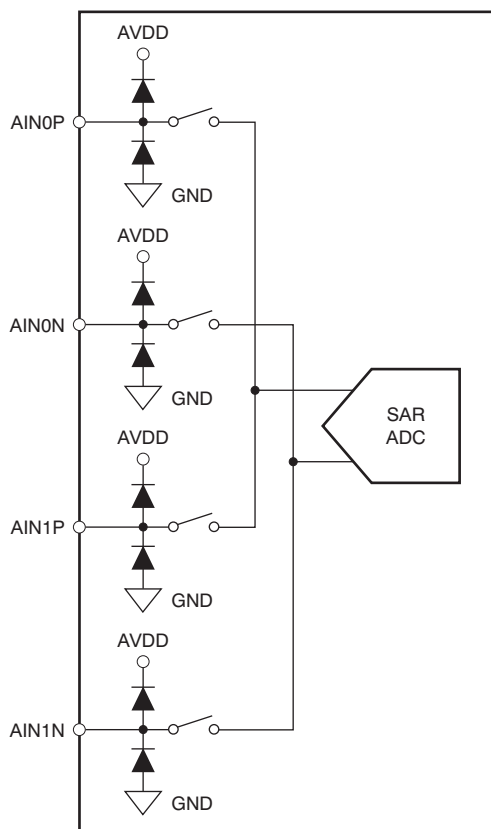


Figure 39. Analog Inputs

Figure 40 shows an equivalent circuit of the multiplexer and ADC sampling stage. The positive and negative inputs are separately sampled on 32-pF sampling capacitors. The multiplexer and sampling switches are represented by an ideal switch in series with a 12-Ω resistance. During sampling, the devices connect the 32-pF sampling capacitor to the ADC driver. This connection creates a glitch at the device input. TI recommends connecting a capacitor across the AINxP and AINxN terminals to reduce this glitch. A driving circuit must have sufficient bandwidth to settle this glitch within the acquisition time.

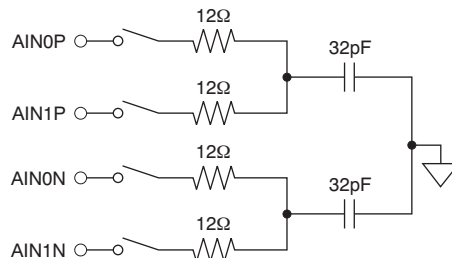
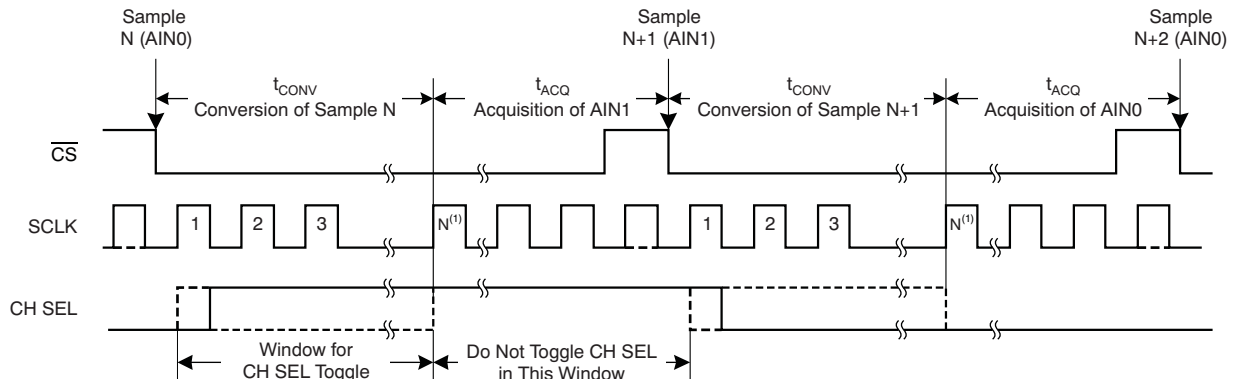


Figure 40. Input Sampling Stage Equivalent Circuit
(See the [Application Information](#) section for details on the driving circuit.)

Feature Description (continued)

Figure 41 shows a timing diagram for the ADC analog input channel selection. As shown in Figure 41, the CH SEL signal selects the analog input channel to the ADC. CH SEL = 0 selects channel 0 (AIN0P – AIN0N) and CH SEL = 1 selects channel 1 (AIN1P – AIN1N). It is recommended not to toggle the CH SEL signal during an ADC acquisition phase until the device detects the first valid SCLK rising edge after the device samples the analog input. If CH SEL is toggled during this period, an erroneous output code can result because the device might detect an unsettled analog input.

CH SEL can be toggled at any time during the window specified in Figure 41; however, TI recommends selecting the desired channel after the first SCLK rising edge and before the second SCLK rising edge. This timing ensures that the multiplexer output is settled before the ADC starts acquisition of the analog input.



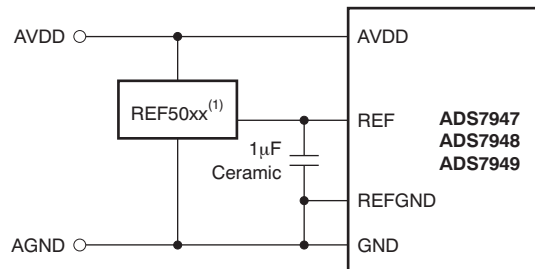
(1) N indicates the 14th SCLK rising edge for the ADS7947 (12 bit), the 11th rising edge for the ADS7948 (10 bit), and the ninth rising edge for the ADS7949 (8 bit).

Figure 41. ADC Analog Input Channel Selection

8.3.2 Reference

The ADS7947, ADS7948, and ADS7949 use an external reference voltage during the conversion of a sampled signal. The devices switch the capacitors used in the conversion process to the reference terminal during conversion. The switching frequency is the same as the SCLK frequency. The REF terminal must be decoupled to REFGND with a 1-μF ceramic capacitor in order to get the best noise performance from the device. The capacitor must be placed closest to these pins. The reference input can be driven with the REF50xx series precision references from TI. Figure 42 shows a typical reference driving circuit.

For convenience, AVDD can be used as a reference. The ADS794x allow reference ranges up to AVDD. However, make sure that AVDD is well-bypassed and that there is a separate bypass capacitor between REF and REFGND.



(1) Select the appropriate device as described by the required reference value. For example, select the REF5040 for a 4-V reference, the REF5030 for a 3-V reference, and the REF5025 for a 2.5-V reference. Ensure that (AVDD – REF) > 0.2 V so that the REF50xx functions properly.

Figure 42. Typical Reference Driving Circuit

Feature Description (continued)

8.3.3 Clock

The ADS794x use SCLK for conversions (typically 34 MHz). A lower frequency SCLK can be used for applications requiring sample rates less than 2 MSPS. However, using a 34-MHz SCLK and slowing down the device speed by choosing a lower frequency for \overline{CS} is better, which allows more acquisition time. This configuration relaxes constraints on the output impedance of the driving circuit. See the [Application Information](#) section for a calculation of the driving circuit output impedance.

8.3.4 ADC Transfer Function

The ADS7947 (12 bit), ADS7948 (10 bit), and ADS7949 (8 bit) devices are unipolar, pseudo-differential input devices. The ADC output is in straight binary format. [Figure 43](#) shows ideal characteristics for this family of devices. Here, FSR is the full-scale range for the ADC input ($A_{INxP} - A_{INxN}$) and is equal to the reference input voltage to the ADC (V_{REF}). 1 LSB is equal to $(V_{REF} / 2^N)$ where N is the resolution of the ADC (for example, $N = 12$ for the ADS7947).

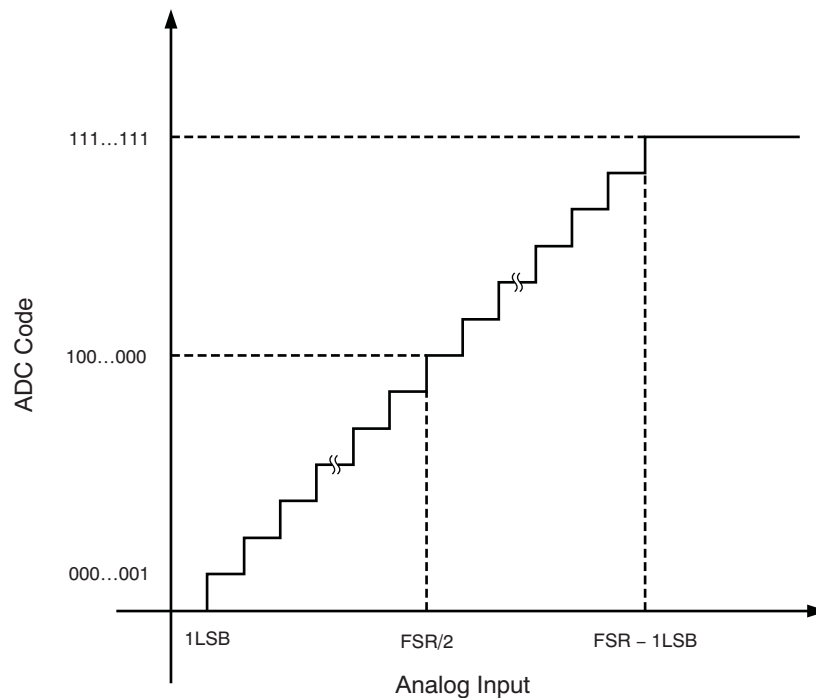


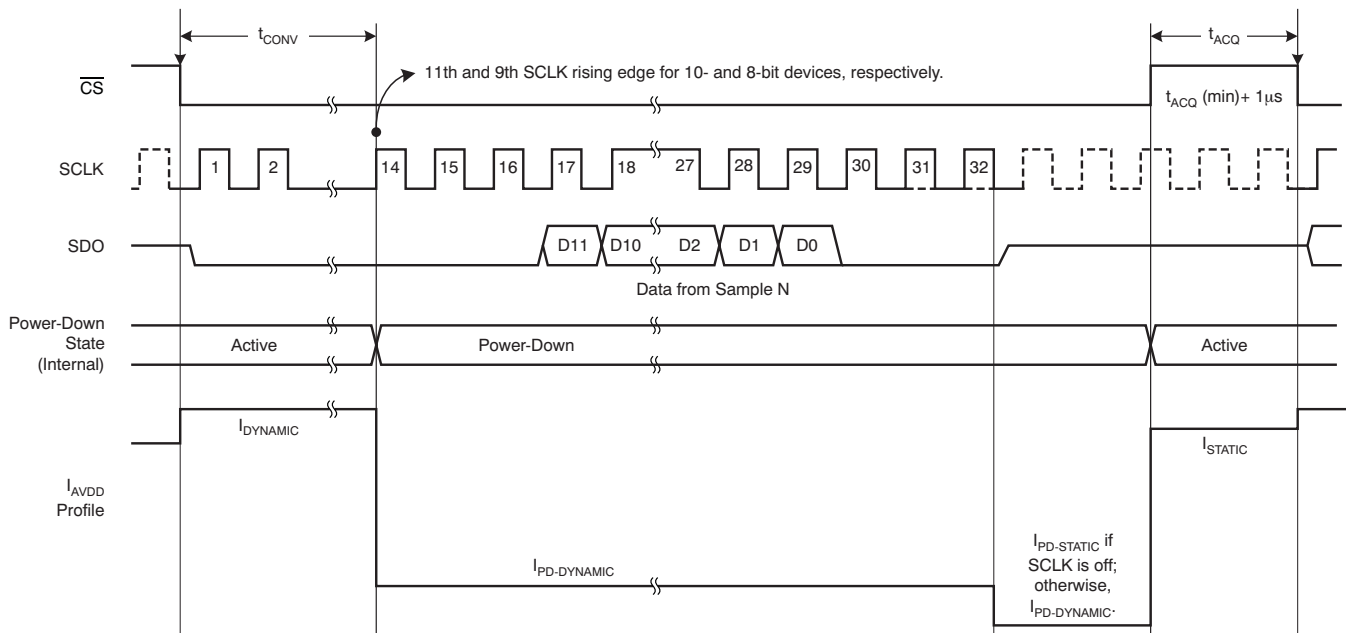
Figure 43. ADS7947, ADS7948, and ADS7949 Transfer Characteristics

8.3.5 Power-Down

The ADS7947, ADS7948, and ADS7949 family of devices offers an easy-to-use power-down feature available through a dedicated PDEN pin (pin 12). A high level on PDEN at the \overline{CS} rising edge enables the power-down mode for that particular cycle. [Figure 44](#) to [Figure 46](#) illustrate device operation with power-down in both 32-clock and 16-clock mode.

Many applications must slow device operation. For speeds below approximately 500 kSPS, the 32-clock mode can be used with power-down. This capability results in considerable power savings.

As illustrated in [Figure 44](#), PDEN is held at a logic '1' level. The device observes the PDEN status only at the \overline{CS} rising edge; however, for continuous low-speed operation, continuously hold PDEN = 1. The devices detect power-down mode on the \overline{CS} rising edge with PDEN = 1.

Feature Description (continued)

Figure 44. Operation With a 32-Clock Frame in Power-Down Mode (PDEN = 1)

On the \overline{CS} falling edge, the devices start normal operation as previously described. The devices complete conversions on the 14th SCLK rising edge. (Conversions complete on the 11th and ninth SCLK rising edge for 10-bit and 8-bit devices, respectively.) The devices enter the power-down state immediately after conversions complete. However, the devices can still output data as per the timings described previously. The devices consume dynamic power-down current ($I_{PD-DYNAMIC}$) during data out operations. TI recommends stopping the clock after the 32nd SCLK falling edge to further save power down to the *static power-down current* level ($I_{PD-STATIC}$). The devices power up again on the SCLK rising edge. However, they require an extra $1\mu s$ to power up completely. \overline{CS} must be high for the $1\mu s + t_{ACQ}$ (min) period.

In some applications, data collection is accomplished in burst mode. The system powers down after data collection. 16-clock mode is convenient for these applications. [Figure 45](#) and [Figure 46](#) detail power saving in 16-clock burst mode.

As illustrated in [Figure 45](#), the two frames capturing the $N-1$ and N th samples are normal 16-clock frames. Keeping $PDEN = 1$ prior to the \overline{CS} rising edge in the next frame ensures that the devices detect the power-down mode. Data from the N th sample are read during this frame. The N th sample represents the last data of interest in the burst of conversions. The devices enter power-down state after the end of conversions. This state is the 14th, 11th, or ninth SCLK rising edge for the 12-, 10-, and 8-bit devices, respectively. The clock can be stopped after the 14th SCLK falling edge; however, TI still recommends stopping the clock after the 16th SCLK falling edge. There must be no more than 29 SCLK falling edges during the \overline{CS} low period. This limitation ensures that the devices remain in 16-clock mode.

The devices remain in a power-down state as long as \overline{CS} is low. A \overline{CS} rising edge with $PDEN = 0$ brings the devices out of the power-down state. Ensure that the \overline{CS} high time for the first sample after power up is more than $1\mu s + t_{ACQ}$ (min).

Feature Description (continued)

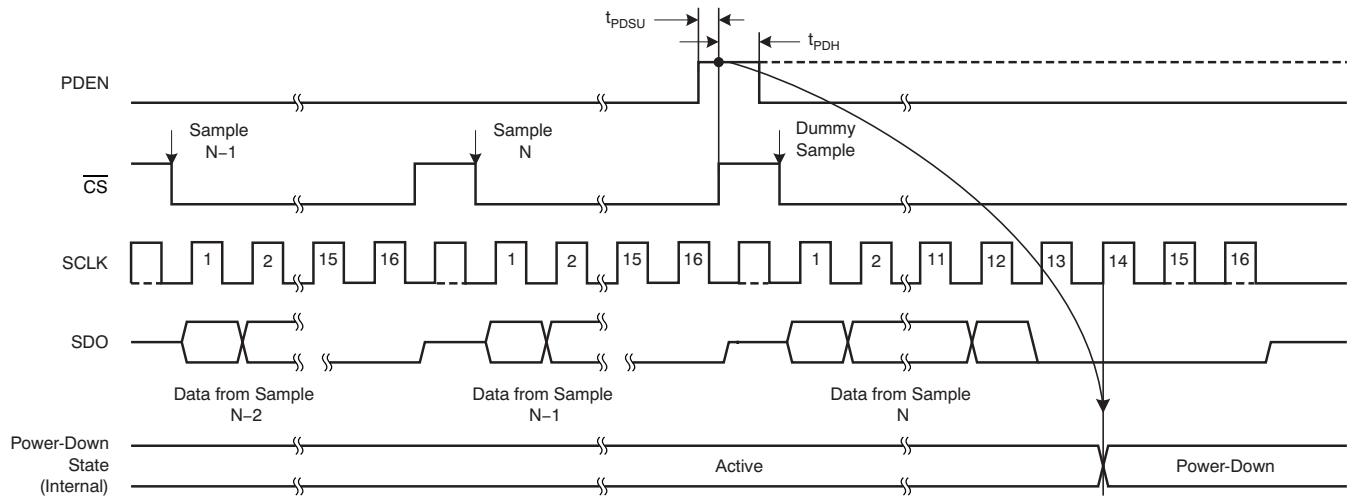


Figure 45. Entry Into Power-Down With 16-Clock Burst Mode

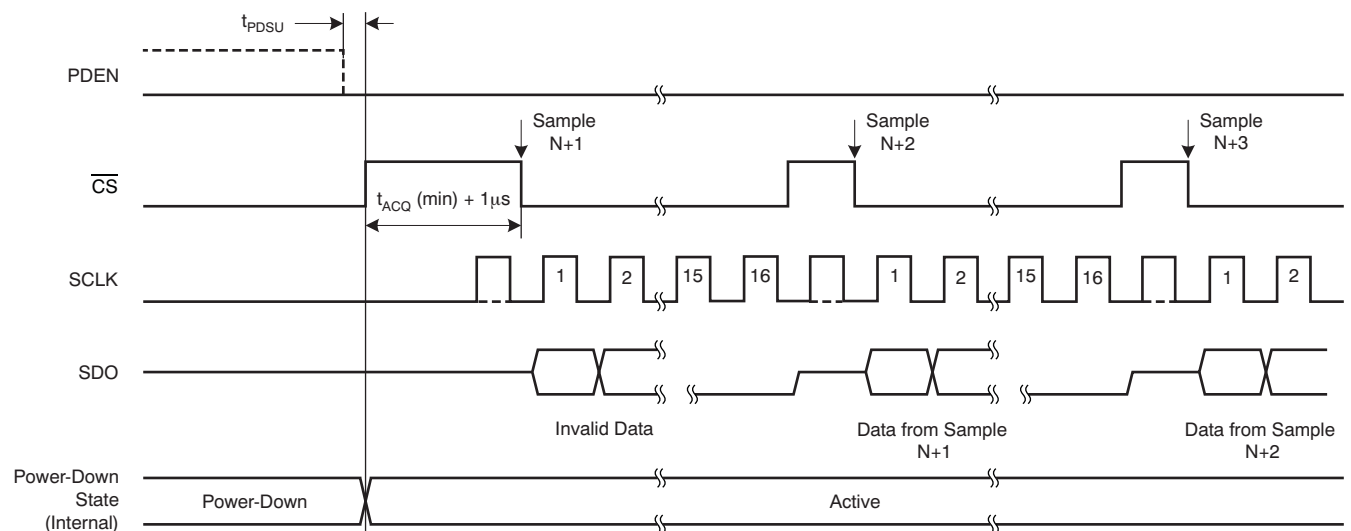


Figure 46. Exit From Power-Down With 16-Clock Burst Mode

8.4 Device Functional Modes

8.4.1 Device Operation

The ADS7947, ADS7948, and ADS7949 are typically operated with either a 16-clock frame or 32-clock frame for ease of interfacing with the host processor.

8.5 Programming

8.5.1 16-Clock Frame

Figure 47 through Figure 49 illustrate the devices operating in 16-clock mode. This mode is the fastest mode for device operation. In this mode, the devices output data from previous conversions while converting the recently sampled signal.

As shown in Figure 47, the ADS7947 starts acquisition of the analog input from the 14th rising edge of SCLK. The device samples the input signal on the \overline{CS} falling edge. SDO comes out of 3-state and the device outputs the MSB on the \overline{CS} falling edge. The device outputs the next lower SDO bits on every SCLK falling edge after the SCLK rising edge. The data correspond to the sample and conversion completed in the previous frame. During a \overline{CS} low period, the device converts the recently sampled signal and uses SCLK for conversions. The number of clocks needed for a conversion for 12-bit and 8-bit devices are different. For the ADS7947, conversion is complete on the 14th SCLK rising edge. \overline{CS} can be high at any time after the 14th SCLK rising edge. The \overline{CS} rising edge after the 14th SCLK rising edge and before the 29th SCLK falling edge keeps the device in the 16-clock data frame. The device output goes to 3-state with \overline{CS} high.

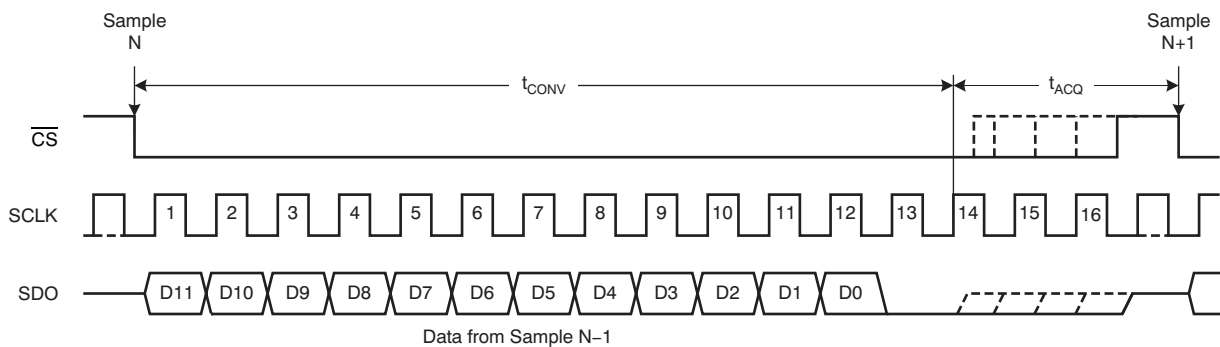


Figure 47. ADS7947 Operating in 16-Clock Mode Without Power-Down (PDEN = 0)

SCLK can also be stopped after the 14th SCLK rising edge.

Figure 48 and Figure 49 illustrate the 16-clock mode operation for the ADS7948 and ADS7949, respectively. The operation for these 10-bit and 8-bit devices is identical to the ADS7947 except that the conversion ends on different edges of SCLK. For the ADS7948, the conversion ends and acquisition starts on the 11th SCLK rising edge. For the ADS7949, the device uses the ninth SCLK rising edge for the conversion end and acquisition start. Similar to the ADS7947, \overline{CS} can go high and SCLK can be stopped when the device enters acquisition.

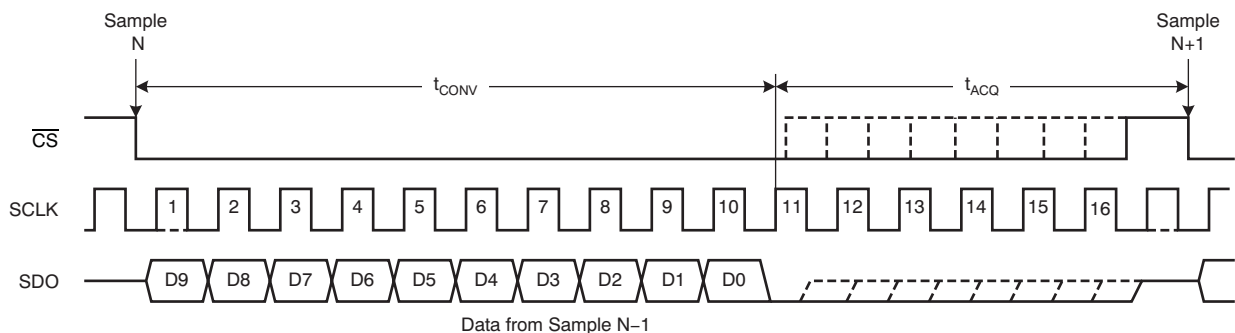


Figure 48. ADS7948 Operating in 16-Clock Mode Without Power-Down (PDEN = 0)

Programming (continued)

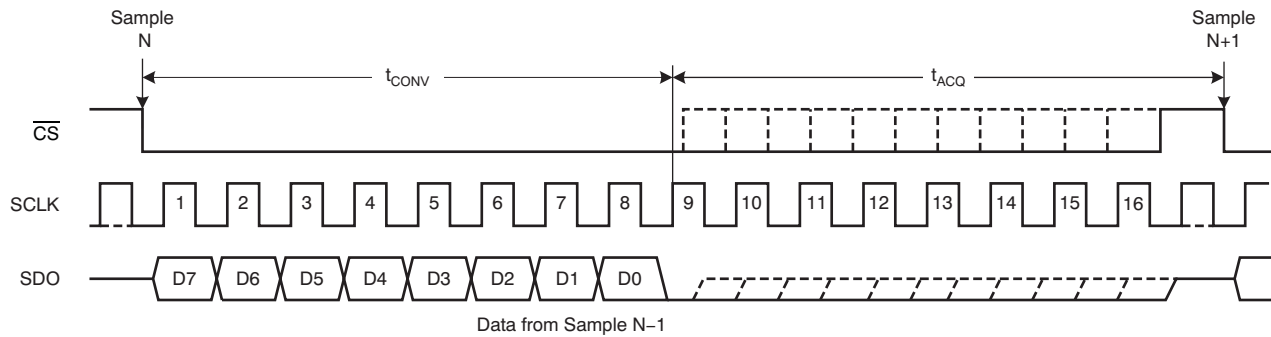


Figure 49. ADS7949 Operating in 16-Clock Mode Without Power-Down (PDEN = 0)

8.5.2 32-Clock Frame

Figure 50 through Figure 52 illustrate the devices operating in 32-clock mode. In this mode, the devices convert and output the data from the most recent sample before taking the next sample.

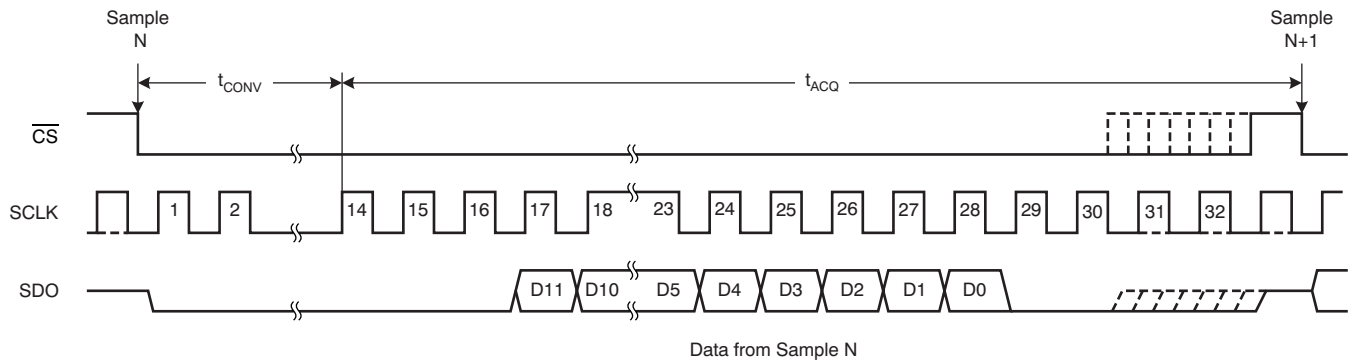


Figure 50. ADS7947 Operation in 32-Clock Frame Without Power-Down (PDEN = 0)

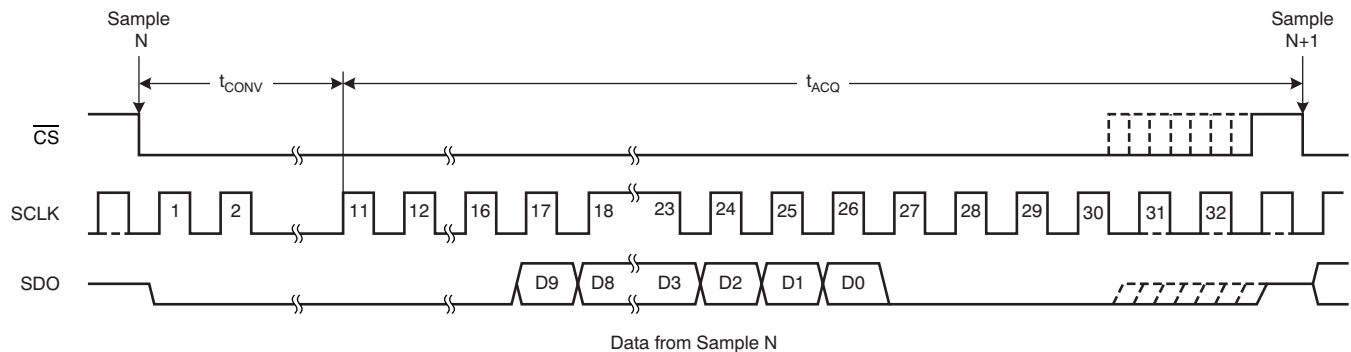


Figure 51. ADS7948 Operating in 32-Clock Frame Without Power-Down (PDEN = 0)

Programming (continued)

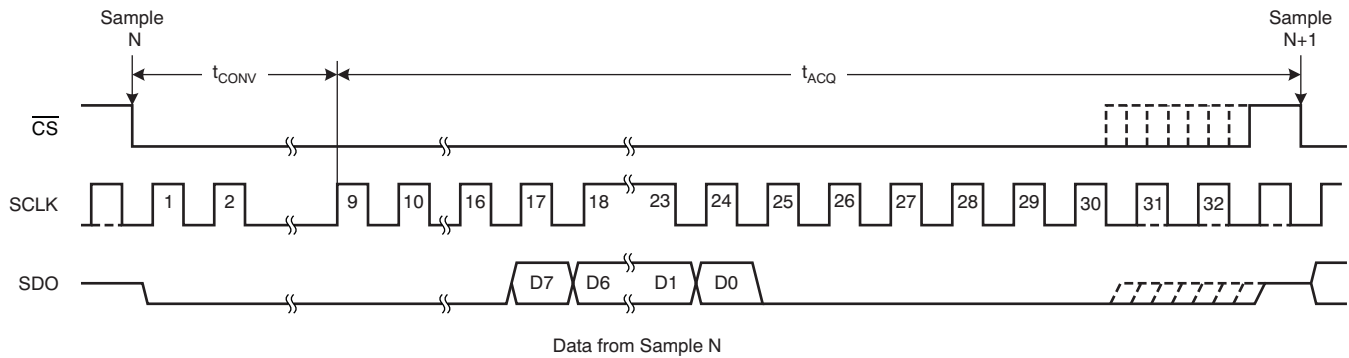


Figure 52. ADS7949 Operating in 32-Clock Frame Without Power-Down (PDEN = 0)

\overline{CS} can be held low past the 16th falling edge of SCLK. The device continues to output recently converted data starting with the 16th SCLK falling edge. If \overline{CS} is held low until the 30th SCLK falling edge, then the device detects 32-clock mode. The device data from recent conversions are already out with no latency before the 30th SCLK falling edge. When 32-clock mode is detected, the device outputs 16 zeros during the next conversion (in fact, for the first 16 clocks), unlike 16-clock mode where the device outputs the previous conversion result. SCLK can be stopped after the device has seen the 30th falling edge with \overline{CS} low.

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The device employs a sample-and-hold stage at the input; see [Figure 40](#) for a typical equivalent circuit of a sample-and-hold stage. The device connects a 32-pF sampling capacitor during sampling. This configuration results in a glitch at the input terminals of the device at the start of the sample. The external circuit must be designed in such a way that the input can settle to the required accuracy during the sampling time chosen. [Figure 53](#) shows a typical driving circuit for the analog inputs.

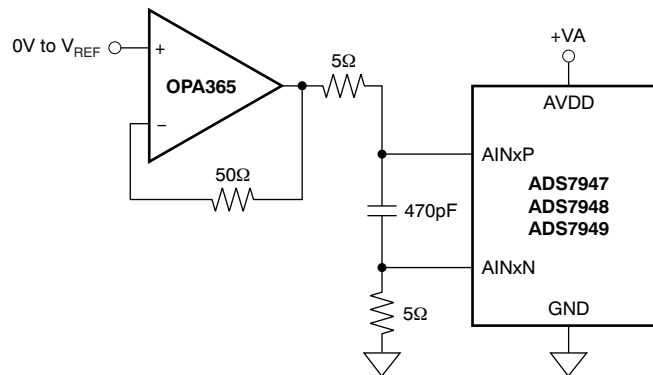


Figure 53. Typical Input Driving Circuit

Application Information (continued)

The 470-pF capacitor across the AINxP and AINxN terminals decouples the driving op amp from the sampling glitch. Splitting the series resistance of the input filter in two equal values is recommended, as shown in [Figure 53](#). Both input terminals are recommended to have the same impedance from the external circuit. The low-pass filter at the input limits noise bandwidth of the driving op amp. Select the filter bandwidth so that the full-scale step at the input can settle to the required accuracy during the sampling time. [Equation 1](#), [Equation 2](#), and [Equation 3](#) are useful for filter component selection.

$$\text{Filter Time Constant (} t_{AU} \text{)} = \frac{\text{Sampling Time}}{\text{Settling Resolution} \times \ln(2)}$$

Where:

Settling resolution is the accuracy in LSB to which the input needs to settle. A typical settling resolution for the 12-bit device is 13 or 14. (1)

$$\text{Filter Time Constant (} t_{AU} \text{)} = R \times C \quad (2)$$

$$\text{Filter Bandwidth} = \frac{1}{2 \times \pi \times t_{AU}} \quad (3)$$

Also, make sure the driving op amp bandwidth does not limit the signal bandwidth below filter bandwidth. In many applications, signal bandwidth can be much lower than filter bandwidth. In this case, an additional low-pass filter can be used at the input of the driving op amp. This signal filter bandwidth can be selected in accordance with the input signal bandwidth.

9.1.1 Driving an ADC Without a Driving Op Amp

There are some low input signal bandwidth applications, such as battery power monitoring or mains monitoring. For these applications, an ADC does not have to be operated at high sampling rates and, preferably, avoid using a driving op amp from a cost perspective. In this case, the ADC input observes the impedance of the signal source (such as a battery or mains transformer). This section elaborates the effects of source impedance on sampling frequency.

[Equation 1](#) can be rewritten as [Equation 4](#):

$$\text{Sampling Time} = \text{Filter Time Constant} \times \text{Settling Resolution} \times \ln(2) \quad (4)$$

As shown in [Figure 54](#), use a bypass capacitor across the positive and negative ADC input terminals.

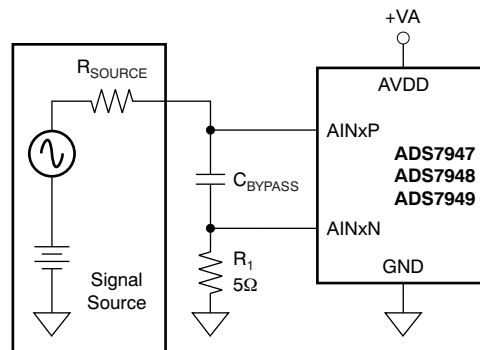


Figure 54. Driving an ADC Without a Driving Op Amp

Source impedance ($R_{SOURCE} + R_1$) with ($C_{BYPASS} + C_{SAMPLE}$) acts as a low-pass filter with [Equation 5](#):

$$\text{Filter Time Constant} = (R_{SOURCE} + R_1) \times (C_{BYPASS} + C_{SAMPLE})$$

Where:

C_{SAMPLE} is the internal sampling capacitance of the ADC (equal to 32 pF). (5)

[Table 1](#) lists the recommended bypass capacitor values and the filter time constant for different source resistances. Use a 10-pF bypass capacitor, at minimum.

Application Information (continued)
Table 1. Filter Time Constant versus Source Resistance

| R_{SOURCE} (Ω) | $R_{SOURCE} + R_1$ | APPROXIMATE C_{BYPASS} (pF) | $C_{BYPASS} + C_{SAMPLE}$ (pF) | FILTER TIME CONSTANT (ns) |
|---------------------------|--------------------|-------------------------------|--------------------------------|---------------------------|
| 15 | 20 | 370 | 400 | 8 |
| 25 | 30 | 235 | 267 | 8 |
| 50 | 55 | 115 | 145 | 8 |
| 100 | 105 | 44 | 76 | 8 |
| 180 | 185 | 10 | 43.2 | 8 |
| 250 | 255 | 10 | 42 | 10.7 |
| 1000 | 1005 | 10 | 42 | 42.2 |
| 5000 | 5005 | 10 | 42 | 210.2 |

Typically, settling resolution is selected as (ADC resolution + 2). For the ADS7947 (12-bit) the ideal settling resolution is 14. Using equations [Equation 2](#) and [Equation 3](#), the sampling time can be easily determined for a given source impedance. This resolution allows 80 ns of sampling time for a 12-bit ADC with 8 ns of filter time constant, which matches the ADS7947 specifications. For source impedances above 180 Ω , the filter time constant continues to increase beyond the 8 ns required for an 80-ns sampling time. This incrementation increases the minimum permissible sampling time for the 12-bit settling and the device must be operated at a lower sampling rate.

The device sampling rate can be maximized by using a 34-MHz clock even for lower throughputs. [Table 2](#) shows typical calculations for the ADS7947(12-bit).

Table 2. Sampling Frequency versus Source Impedance for the ADS7947 (12-Bit)

| R_{SOURCE} (Ω) | C_{BYPASS} (pF) | SAMPLING TIME, t_{ACQ} (ns) | CONVERSION TIME, t_{CONV} (ns) | CYCLE TIME, $t_{ACQ} + t_{CONV}$ (ns) | SAMPLING RATE (MSPS) |
|---------------------------|-------------------|-------------------------------|----------------------------------|---------------------------------------|----------------------|
| 180 | 10 | 80 | 397 (with 34MHz clock) | 477 | 2 |
| 250 | 10 | 107 | 397 (with 34MHz clock) | 504 | 1.98 |
| 1000 | 10 | 422 | 397 (with 34MHz clock) | 819 | 1.2 |
| 5000 | 10 | 2102 | 397 (with 34MHz clock) | 2499 | 0.4 |

An 1000-ns additional sampling time must be allowed over what is shown in [Table 2](#) if PDEN (pin 12) is set high.

10 Power Supply Recommendations

The device has two separate power supplies: AVDD and DVDD. The device operates on AVDD; DVDD is used for the interface circuits. AVDD and DVDD can be independently set to any value within the permissible ranges. Decouple the AVDD and DVDD pins individually with 1- μ F ceramic decoupling capacitors. The decoupling capacitors must be placed as close as possible to the device.

11 Layout

11.1 Layout Guidelines

ADCs are mixed-signal devices. For maximum performance, proper decoupling, grounding, and proper termination of digital signals is essential. Figure 55 shows the essential components around the ADC. All capacitors shown are ceramic. These decoupling capacitors must be placed close to the respective signal pins.

There is a 47-Ω *source series termination* resistor shown on the SDO signal. This resistor must be placed as close to pin 15 as possible. Series terminations for SCLK and CS must be placed close to the host.

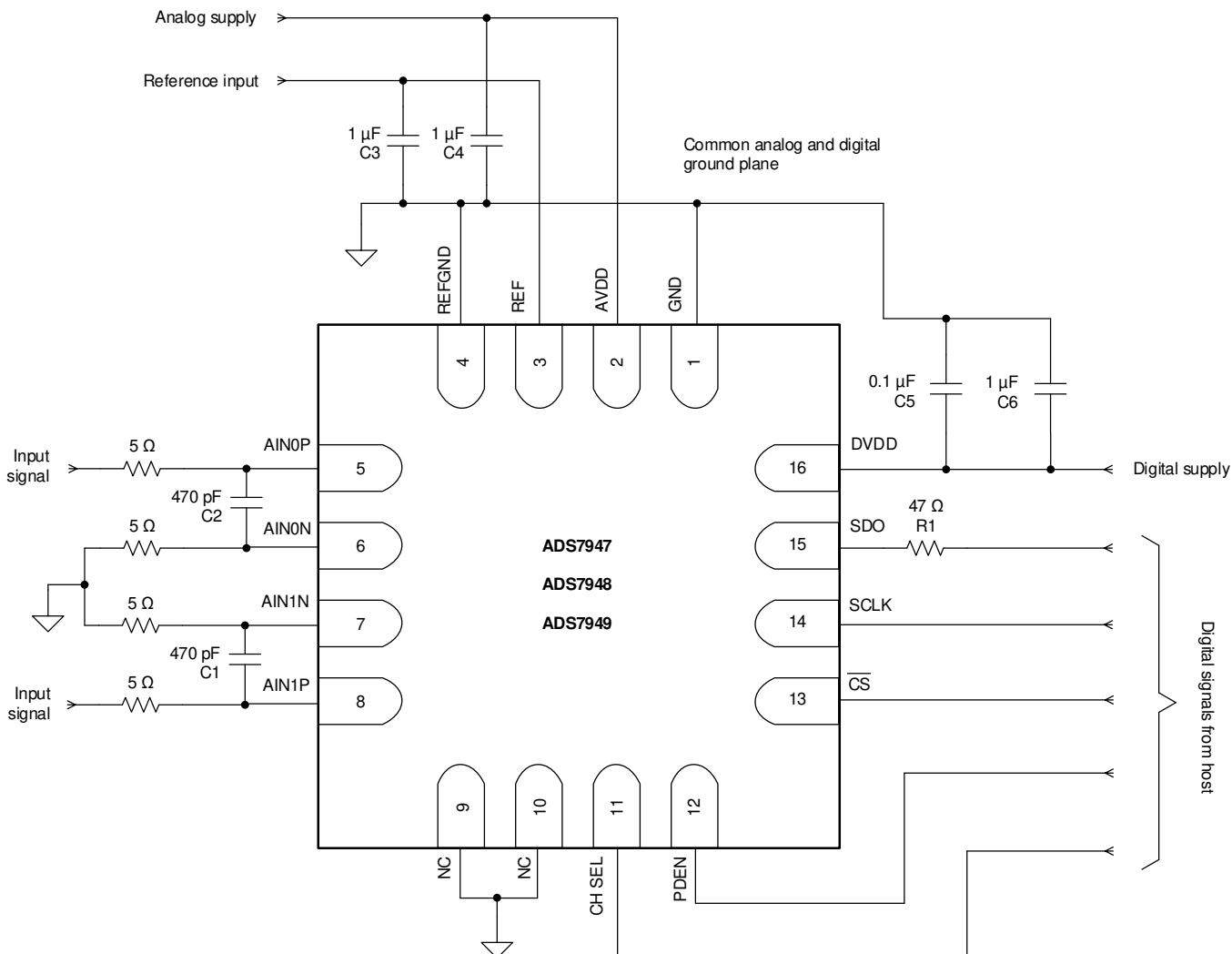


Figure 55. Recommended ADC Schematic

11.2 Layout Example

A common ground plane for both analog and digital often gives better results. Typically, the second PCB layer is the ground plane. The ADC ground pins are returned to the ground plane through multiple vias (PTH). Good practice is to place analog components on one side and digital components on other side of the ADC (or ADCs). All signals must be routed, assuming there is a split ground plane for analog and digital. Furthermore, splitting the ground initially during layout is better. Route all analog and digital traces so that the traces see the respective ground all along the second layer. Then short both grounds to form a common ground plane. [Figure 56](#) shows a typical layout around the ADC.

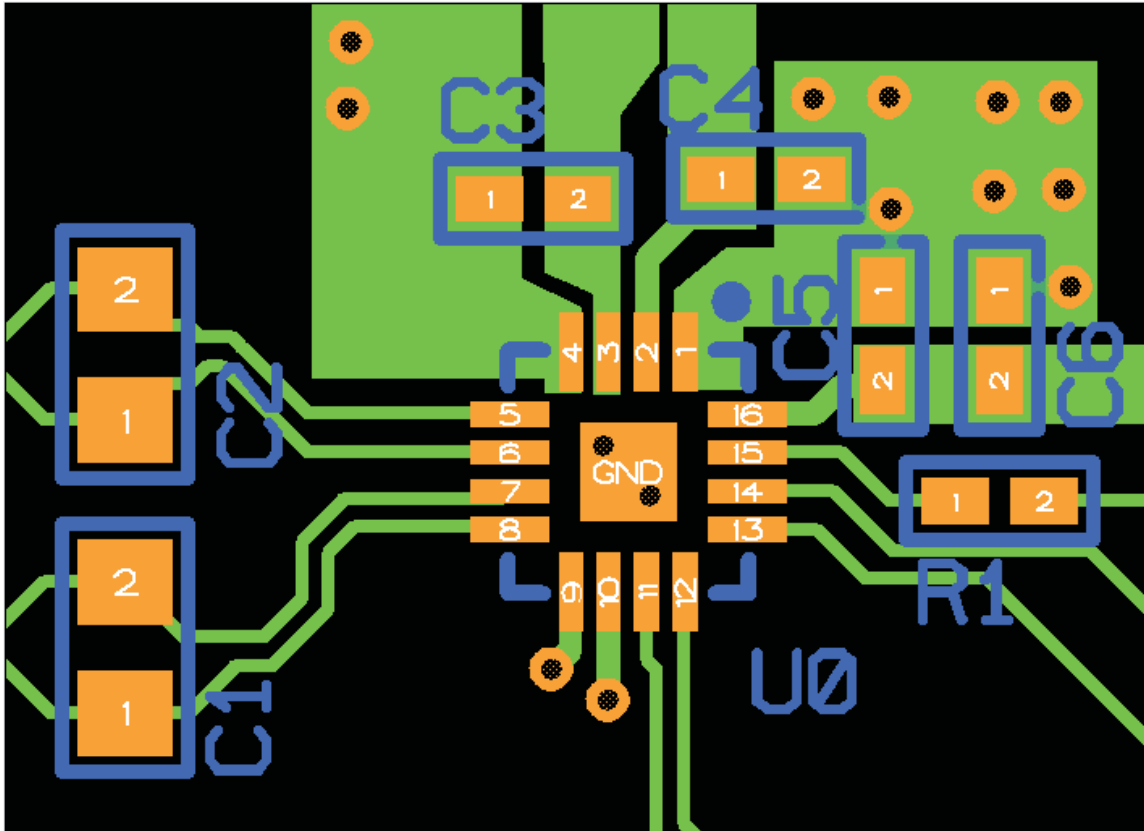


Figure 56. Recommended ADC Layout
(Only top layer is shown, second layer is common ground for analog and digital)

12 Device and Documentation Support

12.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to order now.

Table 3. Related Links

| PARTS | PRODUCT FOLDER | ORDER NOW | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|---------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| ADS7947 | Click here | Click here | Click here | Click here | Click here |
| ADS7948 | Click here | Click here | Click here | Click here | Click here |
| ADS7949 | Click here | Click here | Click here | Click here | Click here |

12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.3 Community Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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12.4 Trademarks

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12.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| ADS7947SRTER | ACTIVE | WQFN | RTE | 16 | 3000 | Green (RoHS & no Sb/Br) | NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | 7947 | Samples |
| ADS7947SRTET | ACTIVE | WQFN | RTE | 16 | 250 | Green (RoHS & no Sb/Br) | NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | 7947 | Samples |
| ADS7948SRTER | ACTIVE | WQFN | RTE | 16 | 3000 | Green (RoHS & no Sb/Br) | NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | 7948 | Samples |
| ADS7948SRTET | ACTIVE | WQFN | RTE | 16 | 250 | Green (RoHS & no Sb/Br) | NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | 7948 | Samples |
| ADS7949SRTER | ACTIVE | WQFN | RTE | 16 | 3000 | Green (RoHS & no Sb/Br) | NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | 7949 | Samples |
| ADS7949SRTET | ACTIVE | WQFN | RTE | 16 | 250 | Green (RoHS & no Sb/Br) | NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | 7949 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| ADS7947SRTER | WQFN | RTE | 16 | 3000 | 330.0 | 12.4 | 3.3 | 3.3 | 1.1 | 8.0 | 12.0 | Q2 |
| ADS7947SRTET | WQFN | RTE | 16 | 250 | 180.0 | 12.4 | 3.3 | 3.3 | 1.1 | 8.0 | 12.0 | Q2 |
| ADS7948SRTER | WQFN | RTE | 16 | 3000 | 330.0 | 12.4 | 3.3 | 3.3 | 1.1 | 8.0 | 12.0 | Q2 |
| ADS7948SRTET | WQFN | RTE | 16 | 250 | 180.0 | 12.4 | 3.3 | 3.3 | 1.1 | 8.0 | 12.0 | Q2 |
| ADS7949SRTER | WQFN | RTE | 16 | 3000 | 330.0 | 12.4 | 3.3 | 3.3 | 1.1 | 8.0 | 12.0 | Q2 |
| ADS7949SRTET | WQFN | RTE | 16 | 250 | 180.0 | 12.4 | 3.3 | 3.3 | 1.1 | 8.0 | 12.0 | Q2 |

TAPE AND REEL BOX DIMENSIONS



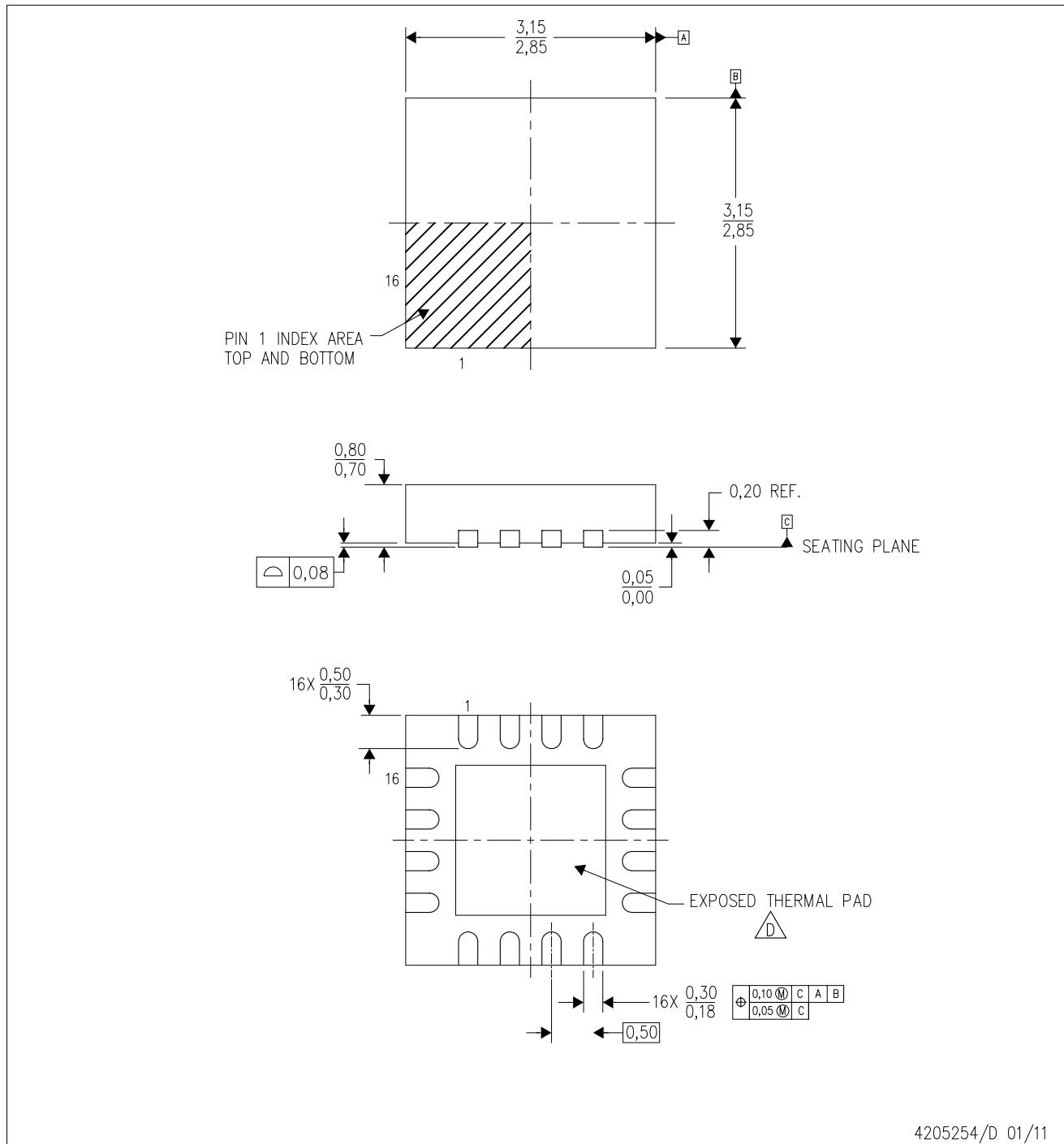
*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| ADS7947SRTER | WQFN | RTE | 16 | 3000 | 367.0 | 367.0 | 35.0 |
| ADS7947SRTET | WQFN | RTE | 16 | 250 | 210.0 | 185.0 | 35.0 |
| ADS7948SRTER | WQFN | RTE | 16 | 3000 | 367.0 | 367.0 | 35.0 |
| ADS7948SRTET | WQFN | RTE | 16 | 250 | 210.0 | 185.0 | 35.0 |
| ADS7949SRTER | WQFN | RTE | 16 | 3000 | 367.0 | 367.0 | 35.0 |
| ADS7949SRTET | WQFN | RTE | 16 | 250 | 210.0 | 185.0 | 35.0 |


MECHANICAL DATA

RTE (S-PWQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



4205254/D 01/11

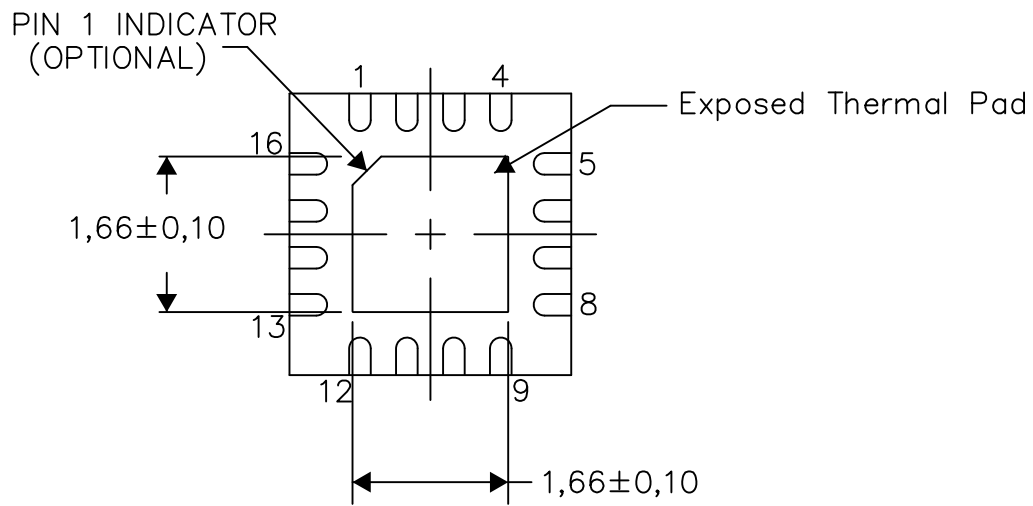
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Quad Flatpack, No-leads (QFN) package configuration.
 -  The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
 - E. Falls within JEDEC MO-220.

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

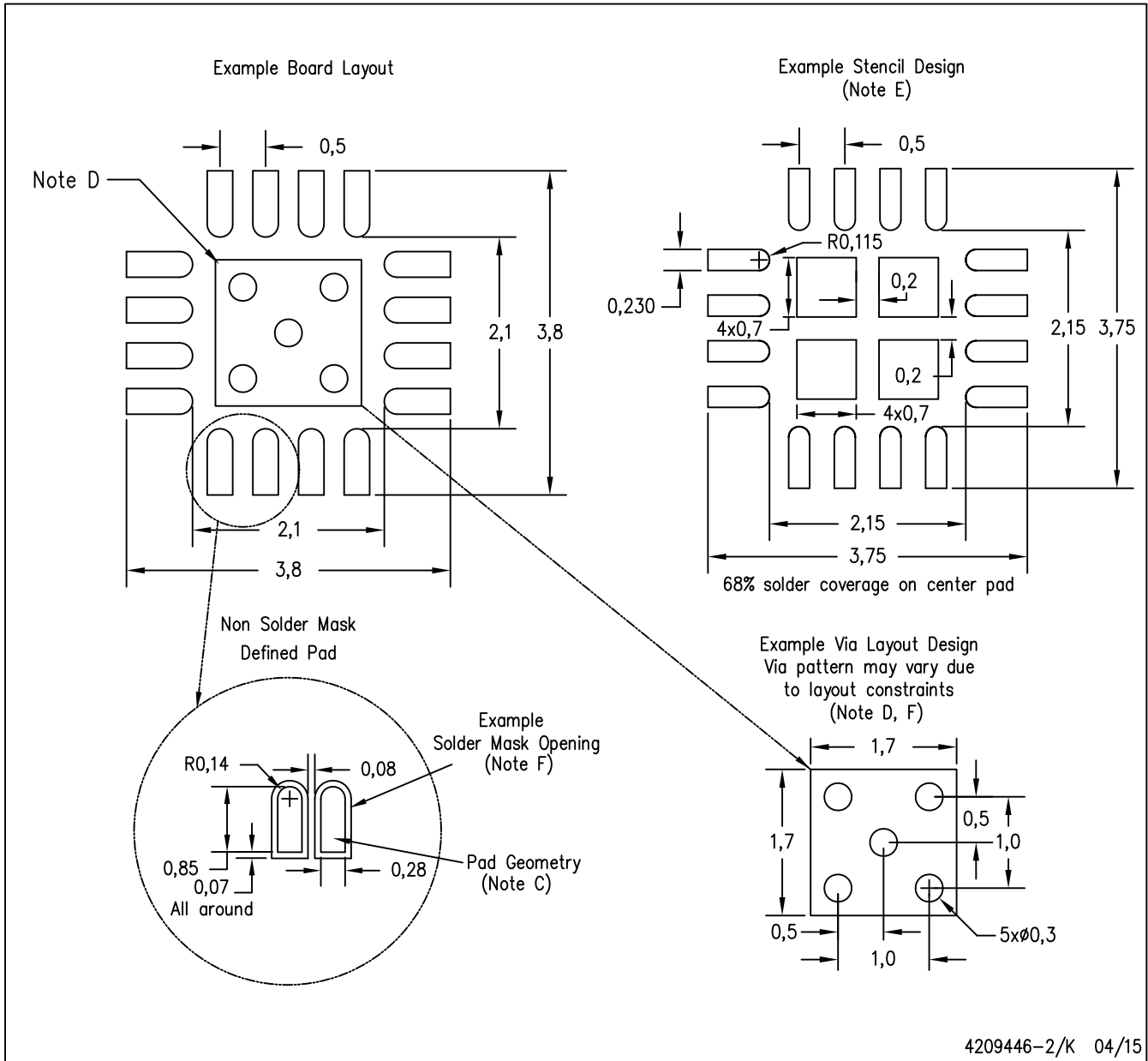
Exposed Thermal Pad Dimensions

4206446-8/U 08/15

NOTE: A. All linear dimensions are in millimeters

RTE (S-PWQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

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